SIDDHARTHA ACADEMY OF HIGHER EDUCATION (Deemed to be University)



M.Tech(VLSI DESIGN and EMBEDDED SYSTEMS) SCHEME OF INSTRUCTION AND SYLLABUS M.Tech SU-24 (w.e.f 2024–2025)

Department of Electronics and Communication Engineering VELAGAPUDI RAMAKRISHNA SIDDHARTHA SCHOOL OF ENGINEERING Kanuru, Vijayawada -520 007, Andhra Pradesh

www.vrsiddhartha.ac.in

VISION

To be a Centre of Excellence in Education, Innovation and Research with Global presence in Arts, Science, Technology, Medicine, Management, Legal and Social Studies in enriching the frontier areas of National and International Importance.

MISSION

To create a transformative educational experience for students focused on problem solving skills, communication abilities, and interpersonal relations and leadership.

To cultivate a vibrant university community for attracting and retaining diverse, worldclass talent creating a collaborative environment open to the free exchange of ideas where research, creativity, innovation and entrepreneurship can flourish and ensuring individuals to achieve their full potential.

To impact society in a pragmatic manner— regionally, nationally, and globally — by engaging with industry, outstanding national and international universities and research organizations.

To be a global University that nurtures excellence in education and innovation for creating a knowledgeable society.

DEPARTMENT VISION

To produce globally competitive and socially sensitized engineering graduates and to bring out quality research in the frontier areas of Electronics & Communication Engineering.

DEPARTMENT MISSION

To provide quality and contemporary education in the domain of Electronics & Communication Engineering through periodically updated curriculum, best of breed laboratory facilities, collaborative ventures with the industries and effective teaching learning process.

To pursue research and new technologies in Electronics & Communication Engineering and related disciplines in order to serve the needs of society, industry, government and scientific community.

PROGRAM OUTCOMES

- PO1 Independently carry out research /investigation and development work to solve practical problems.
- PO2 Write and present a substantial technical report/document.
- PO3 Demonstrate a degree of mastery over the area as per the VLSI Design and Embedded Systems program.
- PO4 Devise and apply appropriate techniques and modern engineering tools to complex engineering activities with an understanding of the limitations
- PO5 Recognize the need for and an ability to engage in lifelong learning to keep oneself abreast of the knowledge to be competent.

VELAGAPUDI RAMAKRISHNA SIDDHARTHA SCHOOL OF ENGINEERING Department of ELECTRONICS AND COMMUNICATION ENGINEERING SCHEME OF INSTRUCTION FOR TWO YEAR PG PROGRAMME [M.Tech SU-24] M.Tech in VLSI DESIGN AND EMBEDDED SYSTEMS

SEMESTER I			Contact Hours: 26				
S. No	Course Category	Course Code	Title of the Course	L	Т	Р	С
1	Programme Core - I	24ECVE501	CMOS VLSI Design(Integrated Course)	2	0	2	3
	Programme Core -	24ECVE502	Design and verification through System				
2	II		Verilog	3	0	0	3
	Programme Core -	24ECVE503					
3	III		ARM controllers for embedded systems	3	0	0	3
		24ECVE504A	Device Modelling		0		
4	Programme Elective	24ECVE504B	IC Fabrication Technology	3		0	3
4	- I	24ECVE504C VLSI signal processing 3		0	U	3	
		24ECVE504D	MEMS				
		24ECVE505A	Embedded Systems Design and				
			Architecture				
5	Programme Elective	24ECVE505B	Embedded C Programming& Peripheral	3	0	0	3
5	- II		Interfacing	3		0	3
		24ECVE505C	Electronics Design: Sensor and Actuators				
		24ECVE505D	Internet of Things for Real time systems				
	Mandatory Learning	24MTUC501					
6	Course		Research Methodology and IPR		0	0	0
7	Laboratory – I	24ECVE581	Digital System Design Lab		0	3	1.5
8	Laboratory - II	24ECVE582	Embedded Systems Design Lab		0	3	1.5
9	Project	24ECVE591	Capstone project-I	0	0	2	1
		Tota	al	16	0	10	19

SEMESTER II

CONTACT HOURS: 28

S. No	Course Category	Course Code	Title of the Course	L	Т	Р	С
1	Programme Core - IV	24ECVE506	Hardware/Software codesign (Integrated course)	2	0	2	3
2	Programme Core - V	24ECVE507	Real Time Operating System	3	0	0	3
3	Programme Core - VI	24ECVE508	Analog & Mixed Signal Design		0	0	3
		24ECVE509A	Low Power VLSI Design				
4	Drogramma Elastiva III	24ECVE509B	Semiconductor Packaging and Testing	3	0	0	3
4	Programme Elective – III	24ECVE509C High level synthesis		3	0	0	3
		24ECVE509D	RF IC Design				
	Programme Elective - IV	24ECVE510A	LINUX Shell Scripting		0	0	
5		24ECVE510B	Embedded Linux Device Drivers	3			3
3		24ECVE510C Communication buses and Interfaces		3	0	0	3
		24ECVE510D	Industrial Product Design				
6	Audit Course	24MTUC502	Technical Report Writing	2	0	0	-
7	Laboratory – I	24ECVE583	Real Time Operating Systems Lab		0	3	1.5
8	Laboratory - II	24ECVE584	Analog & Mixed Signal Design Lab		0	3	1.5
9	Project	24ECVE592	Capstone project-II		0	2	1
10	Term Paper	24ECVE593	Term Paper	0	0	2	1
	Total				0	12	20

SEMESTER III

CONTACT HOURS: 27

		Course					
S. No	Course Category	Code	Title of the Course		Т	Р	С
1	Programme Elective - V	24ECVE601	Students to complete course in any MOOCS platform such as NPTEL	3	0	0	3
2	Internship	24ECVE691	Internship/ Summer training in Research Organizations/Institutions of Higher Learning (After II Sem)	0	0	4	2
3	Project (Part-A)	24ECVE692	24ECVE692 Dissertation/ Industrial Project - Part A		0	20	10
	Total					24	15

*To be continued in the IV Semester

Program Elective V may be completed in semester I or II by satisfying the pre-requisites

SEMESTER IV

CONTACT HOURS: 32

S. No	Course Category	Course Code	Title of the Course	L	Т	Р	С
1	Project (Part-B)	24ECVE693	Dissertation/ Industrial Project	0	0	32	16
	Total					32	16

L – Lecture, T: Tutorial, P – Practical, C – Credits Total Credits:70

Semester	Credits
1	19
2	20
3	15
4	16
Total	70

Note:

1. Student has to carry out a project applying the knowledge and hands on technical skills they have gained through course work and lab sessions in Semester-I under Capstone Project 1

2. Student should carry out literature survey of the selected problem and present it in a Seminar for the yearlong Project Work under Term Paper.

3. Student has to carry out a project applying the knowledge and hands on technical skills they have gained through course work and lab sessions in Semester-II under Capstone Project 2

4. At least one theory course in the I & II semesters can be made as integrated course (Theory coupled with Laboratory).

5. Maximum of three theory courses (40% of courses) can be offered as self-learning courses in each of the First and Second semesters.

SEMESTER I

24ECVE501: CMOS VLSI DESIGN

Course Category:	Program Core-I	Credits:	3
Course Type:	Integrated course	Lecture - Tutorial -Practice:	2-0-2
Prerequisites:	UG VLSI Design	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course	Upon successful completion of the course, the student will be able to:								
outcomes	CO1		emonstrate knowledge in Static and dynamic characteristics of MOS inverter, estimate delay and power. [K2].						
	CO2	Design and an	esign and analyze combinational MOS logic circuits. [K4].						
	CO3	Design and an	sign and analyze MOSFET based sequential logic circuits. [K4]						
	CO4	Design and an	nalyze various	Datapath Subs	ystems. [K4]				
	CO5	Classify diffe	rent semicondu	actor memories	[K3].				
Contribution		PO1	PO2	PO3	PO4	PO5			
of Course									
Outcomes	CO1	2	1	3	3	2			
towards	CO2	2	1	3	3	2			
achievement		_	-	,	C	_			
of Program	CO3	2	1	3	3	2			
Outcomes	CO4	3	1	3	3	3			
(1 – Low, 2 -	004	5	1	5	5	5			
Medium, 3 –	CO5	3	1	3	3	2			
High)									
Course	Unit	1: The CMOS	Inverter			(9 Hrs)			
Content	Intuiti Static Power Invert Unit 2 Introd a Log Unit 3	The MOS (FET) Transistor, Introduction, The Static CMOS Inverter- An Intuitive Perspective, Evaluating the Robustness of the CMOS Inverter, The Static Behavior Performance of CMOS Inverter, The Dynamic Behavior, Power, Energy, and Energy-Delay, Technology Scaling, and its Impact on the Inverter Metrics.Unit 2: Designing Combinational Logic Gates In CMOS(9 Hrs)Introduction, Static CMOS Design, Dynamic CMOS Design, How to Choose a Logic Style(9 Hrs)							
	Introd Multij Unit 4	Introduction, Static Latches and Registers, Dynamic Latches and Registers.Unit 4: Designing Arithmetic Building Blocks(10 Hrs)Introduction, Datapaths in Digital Processor Architectures, the Adder, the Multiplier, the Shifter, Other Arithmetic Operators(10 Hrs)Unit 5: Designing Memory and Array Structures(10 Hrs)Introduction, the Memory Core, Read-Only Memories, Non-volatile Read-							
	Write	Memories, R	ead-Write Mer	mories (RAM)), Contents-Ad				

Text books	Textbooks:
and Reference	 Digital Integrated Circuits – A Design Perspective, Jan M. Rabaey, Anantha Chandrakasan, Borivoje Nikolic, 2nd Edition, PHI.
books	 References: CMOS VLSI Design: A Circuits and Systems Perspective, Neil H. E. Weste, David Money Harris, 4th Edition, Addison- Wesley,2011 Digital Integrated Circuit Design – Ken Martin, Oxford University Press, 2011. CMOS Digital Integrated Circuits Analysis and Design – Sung-Mo Kang, Yusuf Leblebici, TMH, 3rd Ed., 2011.
	 Introduction to VLSI Systems: A Logic, Circuit and System Perspective – Ming-BO Lin, CRC Press, 2011
E-resources and other digital material	 https://www.iitg.ac.in/cseweb/vlab/vlsi/CMOS_theory.html https://sudip.ece.ubc.ca/cadence-virtuoso-schematic-simulations/ https://ocw.mit.edu/courses/6-004-computation-structures-spring- 2017/pages/c3/c3s1/ https://sps.ewi.tudelft.nl/~nick/courses/gs/slides/02_inverter.pdf https://archive.nptel.ac.in/courses/108/107/108107129/ https://ee.iitm.ac.in/vlsi/courses/ee5311_2020 https://github.com/muhammadaldacher/Layout-Design-of-an-8x8- SRAM-array

24ECVE502: DESIGN AND VERIFICATION THROUGH SYSTEM VERILOG

Course Category:	Programme Core -II	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	Digital Logic Design	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course	Upon	Upon successful completion of the course, the student will be able to:							
outcomes	CO1	Understand types. [K3].		of verification	n methodolog	ies and data			
	CO2	Summarize th assertions [K4	sertions [K4].						
	CO3	Analyze the	alyze the concepts of functional coverage. [K5].						
	CO4	•	nalyze the basic concepts OOP. [K5].						
	CO5			rilog testbench		and the use			
				ware verification					
Contribution		PO1	PO2	PO3	PO4	PO5			
of Course Outcomes	CO1	3		3		1			
towards achievement	CO2	2		3		1			
of Program	CO3	3		3		1			
Outcomes	CO4	3		3		1			
(1 – Low, 2 - Medium, 3 – High)	CO5	3		3		1			
Course Content	Verifi Metho Testbo Simul Unit 2 Built Array new t Convo Enum	Unit 1: Verification Guidelines(9 Hrs)Verification process, Basic Testbench functionality, Directed Testing, Methodology Basics, Constrained Random Stimulus, Functional coverage, Testbench components, Layered Testbench, Building layered Testbench, Simulation Environment phases.(9 Hrs)Unit 2: Data Types(9 Hrs)Built in data types, Fixed sized arrays, Dynamic arrays, Queues, Associative Arrays, Linked lists, Array methods, Choosing a storage data type, Creating new types with typedef, Creating user defined structures, Packages, Type Conversion, Enumerated types, Defining Enumerated Values, Routines for Enumerated Types, Converting to and from Enumerated Types, Constant, strings, Expression width							

	Procedural Statements Tasks, Functions, Routine Arguments, Returning from							
	a Routine, Local Data Storage, Time Values							
	Unit 4: Basic OOP and its control(9 Hrs)Basic OOP: Introduction, Thinking of Nouns, Not Verbs, Your First Class, Where to Define a Class, OOP Terminology, Creating New Objects, Object Deallocation Using Objects, Static Variable vs. Global Variable, Class Methods, Defining Methods Outside of the Class, Scoping Rules, Using One Class Inside Another, Understanding Dynamic Objects, Public vs. Local, Straying Off-Course: Building a TestbenchUnit 5: Connecting the Testbench and Design, System Verilog Assertions Separating the testbench and design, Interface constructs, Stimulus timing, Interface driving and sampling, connecting it all together, Top-level scope program – Module interactions, SystemVerilog Assertions: Immediate Assertions, Customizing Assertion Actions, Concurrent Assertions, Exploring Assertions.							
Text books	Textbooks:							
and	1. "SystemVerilog for Verification: A Guide to Learning the Testbench							
Reference	Language Features" by Chris Spear and Greg Tumbush (3 rd Edition,							
books	2012)							
	References:							
	 "SystemVerilog Assertions and Functional Coverage: Guide to Language, Methodology and Applications" by Ashok B. Mehta (2nd Edition, 2016) 							
	 "SystemVerilog for Design" by Stuart Sutherland, Simon Davidmann, and Peter Flake (2nd Edition, 2006) 							
	 3. "The SystemVerilog Primer: An Introduction to SystemVerilog for Hardware Design and Verification" by J. Bhasker (4th Edition, 2019) "Advanced Digital Design with the Verilog HDL" by Michael D. Ciletti (2nd Edition, 2010) 							
E-resources	1. https://youtu.be/_5PJMHmSfgc?si=Cc0ice970woPw6pB							
and other	2. <u>https://verificationguide.com/systemverilog-examples/systemverilog-</u>							
digital	testbench-example-with-scb/							
material	3. <u>https://www.youtube.com/watch?v=5LUQxIDRsRI</u>							
	4. <u>https://www.doulos.com/knowhow/systemverilog/systemverilog-</u>							
	tutorials/							
	 <u>https://www.systemverilog.in/</u> <u>https://www.chipverify.com/tutorials/systemverilog</u> 							
	o. <u>https://www.ompverity.com/tutorials/systemveritog</u>							

24ECVE503: ARM CONTROLLERS FOR EMBEDDED SYSTEMS

Course Category:	Program Core-III	Credits:	3
Course Type: Theory		Lecture - Tutorial -Practice:	3-0-0
Prerequisites: -		Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course	Upon successful completion of the course, the student will be able to:								
outcomes	CO1	philosophy, i	Describe the ARM processor architecture and explain its design philosophy, including key components such as registers, CPSR, and pipeline structures. [K2].						
	CO2		Apply ARM and Thumb instruction sets to write assembly language programs, [K3]						
	CO3	-	zed C program ramming techn	s and ARM ass iques.[K6]	sembly code b	y employing			
	CO4	Analyze and i in ARM syste		eption and inter	rrupt handling	mechanisms			
	CO5			protection uni in embedded s		l memory			
Contribution		PO1							
of Course Outcomes	CO1			2					
towards achievement	CO2			2					
of Program Outcomes	CO3				2				
Outcomes	CO4					1			
(1 – Low, 2 - Medium, 3 –	CO5					2			
High)						2			
Course	UNI	Γ I: ARM Pro	cessor Fundar	nentals		(8 Hrs)			
Content		Processor Fu		0	1 .	0			
		Current Pro upts, and Vector			line Structure	, Exceptions,			
		2: Instruction	-	2		(8 Hrs)			
		duction to the			0				
		h Instructions, Program Status			tware Interrup	ot Instruction,			
	Intro	duction to the	Thumb Instru	iction Set: Thu	-	-			
		ctions, Data F ctions, Softwar	-		1-Store Instru	chons, Stack			
		3: Efficient C I	-		embly Code (Optimization			
	(10 H	rs)							

	Efficient C Programming: Basic C Data Types, C Looping Structures,
	Register Allocation, Function Calls, Structure Arrangement
	Writing and Optimizing ARM Assembly Code: Writing Assembly Code, Profiling and Cycle Counting, Instruction Scheduling, Register Allocation, Conditional Execution, Looping Constructs
	Unit 4: Exception and Interrupt Handling, Cache Memory(9 Hrs)Exception and Interrupt Handling: Exception Handling, Interrupts, InterruptHandling SchemesCache Memory: The Memory Hierarchy and Cache Memory, Cache,architecture, Cache Policy, Flushing and Cleaning Cache MemoryUnit 5: Memory Protection and Management UnitsMemory Protection Units (MPUs): Protected Regions, Initializing the MPU,Caches and Write Buffer
	Memory Management Units (MMUs): Transitioning from an MPU to an MMU, Virtual Memory Concepts, ARM MMU Details, Page Tables, Translation Lookaside Buffer (TLB), Domains and Memory Access Permissions, The Fast Context Switch Extension (FCSE)
Text books and Reference books	 Textbooks: A.Sloss, D.Symes, C.Wright, "ARM system Developers Guide: Designing and Optimizing System Software", Morgan Kaufmann publishers, 2012 References: Steve Furber, "ARM System on Chip Architecture", 2nd ed., Addison
	Wesley Professional,2000.
	 Valvano, J,"Embedded microcomputer systems: real time
	interfacing", 3 rd Edition, Cengage Learning, 2011.
	 Frank Vahid, TonyGivargis, "Embedded System Design", J Wiley India,2005.
E-resources	1. https://community.arm.com/arm-community-blogs/b/architectures-and-
and other	processors-blog/posts/getting-started-with-arm-microcontroller-resources
digital	2. <u>https://www.geeksforgeeks.org/arm-processor-and-its-features/</u> https://double.com/double.com/double.com/102274/lotest/instruction.geta
material	3. <u>https://developer.arm.com/documentation/102374/latest/Instruction-sets-</u> in-the-Arm-architecture
	4. https://www.intel.com/programmable/technical-pdfs/654202.pdf
	5. <u>https://www.intel.com/content/dam/www/programmable/us/en/pdfs/liter</u>
	ature/third-party/archives/ddi0100e_arm_arm.pdf
	6. https://www.embedded.com/reliable-programming-in-arm-assembly-
	language/
	7. <u>https://developer.arm.com/documentation/dui0056/d/handling-processor-exceptions</u>

Course Category:	Program Elective -I	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	Basic electronics and	Continuous Evaluation:	40
	electrical circuits and	Semester end Evaluation:	60
	devices, electronics	Total Marks:	100
	properties of		
	semiconductor materials,		
	fundamental law and		
	concepts of electrostatics		
	physics		

24ECVE504A: DEVICE MODELING

Course	Upon	successful completion of the course, the student will be able to:						
outcomes	CO1		Understand MOS capacitor working principles, modes of operations, electrostatics of MOS, and leakage in it.[K2]					
	CO2	•	Analyze the physics the current-voltage characteristics of MOSFET, reliability issues, and advanced MOSFETs.[K4]					
	CO3	intrinsic MOS	Understand the principles of Silicon on Insulator MOSFET, analyse intrinsic MOSFET capacitances and resistances, and evaluate FDSOI MOS and its sub-threshold slope.[K2]					
	CO4	Understand the theory of Ballistic nano transistors, evaluate the modeling of Ballistic planer and nanowire-FET, and analyze advanced MOSFETs such as Strain Engineered Channel materials, Electrostatics of double gate, and Fin-FET device.[K2]						
	CO5	Apply the optoelectronic						
Contribution		PO1	PO2	PO3	PO4	PO5		
of Course Outcomes	CO1	2		2		2		
towards achievement	CO2	2		2		2		
of Program	CO3	1		2		2		
Outcomes	CO4	3		2		2		
(1 – Low, 2 – Medium, 3 –	CO5	3		2		2		
High)								
Course Content	Electr MOS	Init 1: MOS Transistor Basics(9 Hrs)lectrons and holes in silicon, Energy band diagram of PN Diode, Types ofIOSFET, MOSFET Mode of Operations, CV characteristics of MOS						
	-	capacitor, Low frequency and high frequency capacitor-voltage characteristics, Non-idealities in MOS, Oxide fixed charges, interfacial						

	charges, Poly-Silicon contact, and poly silicon properties, Electrostatics of non-uniform substrate doping, carrier transport in insulating films, ultrathin							
	gate-oxide.							
	Unit 2: MOSFET (9 Hrs)							
	Drift-Diffusion Approach for current-voltage analysis, Gradual Channel							
	Approximation, channel conductance, trans conductance, MOSFET							
	equivalent circuit ,Sub-threshold current and slope, Body effect, mobility							
	behavior, temperature behaviors MOSFET two dimensional effects, Buried							
	channels, effect of ion implantation on threshold voltage, High field effects							
	and MOSFET reliability issues							
	Unit 3: SOI (Silicon on Insulator) (9 Hrs) Leakage mechanisms in thin gate oxide, High-K-Metal Gate MOSFET devices							
	and technology issues, Intrinsic MOSFET capacitances and resistances, SOI,							
	FDSOI and PDSOI, VT definitions, Back gate coupling and body effect							
	parameter, I-V characteristics of FDSOI-FET, FDSOI-sub-threshold slope,							
	Floating body effect, SOI materials: sapphire, zirconia, spinel, and calcium							
	fluoride.							
	Unit 4: Advanced Nano-Transistors (9 Hrs)							
	Modern bipolar transistor structures, Quasi Ballistic & Ballistic							
	Transports, Theory of ballistic nano transistors, Ballistic planer and							
	nanowire-FET modeling, Semi-classical and quantum treatments							
	Advanced MOSFETs, Electrostatics of double gate, and Fin-FET							
	device high-k/metal gate Fin-FETUnit 5: Device Application(9 Hrs)							
	Unit 5: Device Application (9 Hrs) Introduction, Photoconductor, Photodiodes, Phototransistor, Metal-							
	Semiconductor-Metal Photodetector, Quantum-Well Infrared Photodetector							
Text books	Textbooks:							
and	1. S.M. Sze & Kwok K. Ng, Physics of Semiconductor Devices, Wiley							
Reference	2. B. G. Streetman, S. K. Banerjee, Solid State Electronic Devices,							
books	Pearson, (2016)							
	3. Jean-Pierre Colinge Silicon-on-Insulator Technology: Materials to							
	VLSI, Springer Science Business Media, LLC References:							
	1. N. Arora, MOSFET modeling for VLSI Simulation: Theory and							
	Practice, World.							
	2. Mark S. Lundstrom and Jing Guo Nanoscale Transistors Device							
	Physics, Modeling and Simulation, Springer.							
	3. Yannis Tsividis, Operation and Modeling of the MOS Transistor,							
	Oxford University Press.							
E-resources	1. <u>https://web.mit.edu/6.012/www/SP07-L8.pdf</u>							
and other	2. <u>https://www.chu.berkeley.edu/wp-content/uploads/2020/01/Chenming-</u>							
digital	<u>Hu ch6-1.pdf</u> 3. <u>https://www.researchgate.net/publication/263889224 SILICON ON IN</u>							
material	SULATOR TECHNOLOGY REVIEW							
	4. https://www.slideshare.net/slideshow/simulation-modelling-							
	31263694/31263694							
	5. https://nanohub.org/resources/35870/download/Fundamentals_of_Nanotr							
	ansistors.pdf							
	6. <u>https://www.rp-</u>							
	photonics.com/metal_semiconductor_metal_photodetectors.html							

24ECVE504B: IC FABRICATION TECHNOLOGY

Course Category:	Program Elective -I	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	VLSI Design	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course	Upon successful completion of the course, the student will be able to:							
outcomes	CO1	Discuss the f [K2].	Discuss the fundamentals involved in the VLSI fabrication process [K2].					
	CO2	Analyse diffe [K4].	Analyse different lithography methods, Oxidation and etching process [K4].					
	CO3	Explain the fi	lm deposition a	and diffusion n	nechanisms [K2	2].		
	CO4	Understand th	ne ion implanta	tion and metal	lization process	s [K2].		
	CO5	Impart know technology [k	-	metallization	and back end	l processing		
Contribution		PO1	PO2	PO3	PO4	PO5		
of Course								
Outcomes	CO1	3	2	2	1	2		
towards	CO2	3	3	2	1	2		
achievement			_					
of Program	CO3	3	2	2	1	1		
Outcomes	CO4	3	2	1	1	1		
(1 – Low, 2 -	004	5	2	1	1	1		
Medium, 3 –	CO5	3	3	1	2	1		
High)								
Course	Unit	1: Introductio	n to IC Techn	ology		(8 Hrs)		
Content	Basics of wafer preparation and crystal growth, Electronic grade silicon, Czochralski crystal growing process, Introduction of epitaxy, Vapor phase epitaxy, Molecular beam epitaxy, Silicon-on-insulators, Epitaxial evaluation Unit 2: Oxidation, Lithography and Etching (10 Hrs) Introduction of oxidation process, First order planar growth mechanism and							
	kinetics, Effect of pressure and crystal orientation on growth kinetics, 2D oxide growth kinetics, Poly-silicon oxidation, silicide and silicon nitride oxidation, Advanced defect models related to oxidation induced defects, Introduction of lithography and properties of photoresists, Optical lithography, Electron lithography, XRay lithography, Ion lithography, Fundamentals of plasma etching, Plasma properties, Feature size control and anisotropic etch mechanisms, Reactive plasma etching techniques							
	Unit 3	3: Thin Film E	Deposition			(9 Hrs)		

	Basics of different Chemical and Physical vapour deposition techniques, Film							
	deposition methods for Polysilicon, Silicon dioxide, Silicon Nitride, Metal							
	depositions.							
	Unit 4: Diffusion and Ion Implantation(9 Hrs)							
	Introduction of diffusion, Models of diffusion in solids, in damage annealing,							
	in polycrystalline silicon, and in SiO2, Ion Implantation: Introduction, Range							
	theory, Implantation equipment, Annealing, Shallow junctions, High-energy							
	implantation, Limitation and future scope of ion implantation.							
	Unit 5: Metallization and Back End Processing (9 Hrs)							
	(> 11.6)							
	Metallization: Introduction, Metallization choices, Physical vapor deposition,							
	Patterning, Back-end-process: Introduction, Contacts, Interconnects and Vias,							
	Source, Drain and Gate Contacts.							
Text books	Textbooks:							
	1. S.M.Sze, "VLSI Technology (2nd edition), McGraw Hill, 2003.							
and								
Reference	2. W. Wolf, "Modern VLSI Design", (3rd edition), Pearson,2002.							
books	References:							
	1. Plummer (2001), "Silicon VLSI Technology: Fundamentals, Practice,							
	and Modeling", Pearson Education India.							
	2. C.Y. Chang and S.M.Sze (Ed), (1996), "ULSI Technology", McGraw							
	Hill Companies Inc. 3. Stephen Campbell (2012), "The Science and							
	Engineering of Microelectronics", Oxford University Press.							
E-resources	1. Lecture Series on VLSI Design by Dr.Nandita Dasgupta, Department of							
and other	Electrical Engineering, IIT Madras. <u>http://nptel.ac.in</u>							
digital								
material	2. https://archive.nptel.ac.in/courses/113/106/113106062/							
	3. https://www.youtube.com/watch?v=Hp4xFkEZUos&list=PL5060CE8							
	F13023479							

24ECVE504C: VLSI SIGNAL PROCESSING

Course Category:	Program Elective -I	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	DSP,VLSI	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course	Upon successful completion of the course, the student will be able to:							
outcomes	CO1	Apply pipelining and parallel processing techniques to the design of FIR digital filters and low-power systems. [K3]						
	CO2	•	Solve systems of inequalities related to retiming and apply retiming techniques to optimize digital systems [K3].					
	CO3	11.7		ns and register ularly in multir		1		
	CO4	Develop and	design systolic	architectures f	or FIR filters a	nd matrix		
		-	n, effectively se ntations with d	electing schedu elays [K6].	ling vectors and	d handling		
	CO5	Implement a	nd design fast	convolution a	algorithms, un	derstand the		
				om, Winograd,		•		
				te efficient con	-			
Contribution		PO1	PO2	PO3	PO4	PO5		
of Course Outcomes	CO1	2	2	2				
towards achievement	CO2	2	2	2				
of Program	CO3	3	2	3	2			
Outcomes	CO4	3	2	2	2			
(1 – Low, 2 -	005	2	2	2	2			
Medium, 3 –	CO5	3	2	2	2			
High)								
Course	Unit	l: Pipelining a	nd Parallel Pr	ocessing		(9 Hrs)		
Content	Introd	uction, Pipelin	ing of FIR, Dig	gital Filters, Par	allel processin	· · · ·		
		arallel Processi 2: Retiming	ng for low pow	ver		(0 U ma)		
		0	tion and Prop	erties, Solvir	ng System of	(9 Hrs) Inequalities.		
	Retim	ing Technique	s					
		3: Unfolding &				(9 Hrs)		
		U		folding, Proper		0		
	Foldin			pplication of Ver Minimizati		es, Register		

	Minimization Technique in Folded Architectures, Folding in Multirate							
	Systems Unit 4: Systolic Architecture Design (9 Hrs)							
	Introduction, Systolic Array design Methodology, FIR Systolic Arrays,							
	Selection of scheduling Vector, Matrix Multiplication, 2D Systolic Array Design, Systolic Design for Space Representations containing delays							
	besign, systeme besign for space representations containing delays							
	Unit 5: Fast Convolution (9 Hrs)							
	Introduction, Cook-Toom Algorithm, Winogard Algorithm, Iterated Convolution, Cyclic Convolution, Design of fast convolution							
Text books	Textbooks:							
and	1. Keshab K. Parhi,"VLSI Digital Signal Processing Systems", Wiley-							
Reference	InterSciences, 1999							
books	References:							
	1. Kung. S.Y., H.J. While house T.Kailath, VLSI and Modern							
	singalprocessing, Prentice Hall, 1985							
	2. Jose E. France, Yannis Tsividls, Design of Analog Digital VLSI							
	Circuitsfor Telecommunications and Signal Processing' Prentice Hall,							
	1994.Ramesh, S. (2013). Engineering chemistry (2nd ed.). Wiley India.							
E-resources	1. https://www.win.tue.nl/~wsinmak/Education/2IN35/Parhi/chap3.pdf							
and other	2. <u>http://twins.ee.nctu.edu.tw/courses/vsp_12/lecture/VSP-lec01-</u>							
digital	pipelining%20&%20retiming.pdf							
material	3. <u>https://www.oreilly.com/library/view/vlsi-digital-</u>							
	<u>signal/9780471241867/sec-</u>							
	4.4.html#:~:text=Cutset%20retiming%20only%20affects%20the,4.4(a).							
	4. <u>http://www.ece.umn.edu/users/parhi/SLIDES/chap4.pdf</u>							
	5. <u>https://www.eecs.harvard.edu/htk/static/files/1978-cmu-cs-report-kung-</u>							
	leiserson.pdf							
	6. <u>https://dsp-book.narod.ru/DSPMW/08.PDF</u>							

24ECVE504D: MEMS

Course Category:	Program Elective -I	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	Analog Electronics,	Continuous Evaluation:	40
	Linear Integrated Circuit	Semester end Evaluation:	60
	Applications	Total Marks:	100

Course	Upon successful completion of the course, the student will be able to:						
outcomes	CO1		Understand the basics of MEMS technology and micro actuation methods [K2].				
	CO2	-	Comprehend and analyze microsystem design mechanics, scaling laws, and packaging technologies [K4].				
	CO3	Analyze the microsystems	techniques 5 [K4].	involved in	designing an	d packaging	
	CO4		ferent steps in I micromachini			on, materials	
	CO5	Understand N	MEMS switch ications. [K4]			principles for	
Contribution		PO1	PO2	PO3	PO4	PO5	
of Course Outcomes	CO1	2		1		2	
towards achievement	CO2	2		3		2	
of Program Outcomes	CO3	3		2		2	
	CO4	1		2		2	
(1 – Low, 2 - Medium, 3 – High)	CO5	3		3		2	
Course		1: Introductio		I	I	(9 Hrs)	
Content			MS and Micro				
	Miniaturization, Advantages of MEMS, Working principles of acoustic wave,						
		biomedical, pressure, thermal sensors, Micro actuation: Basics of actuation,					
		thermal forces, shape memory alloys, piezoelectric crystals, electrostatic forces, Micro grippers, micro motors, micro pumps, Bending movement and					
		, concept of mi) r	. ,		
		-	for Microsyste	ms Design and	d Scaling Law	vs (9 Hrs)	
		-	hin plates, Me				
			, Thin film m				
	Scalir	ig laws in min	iaturization: so	caling in geom	etry, rigid bo	dy dynamics,	

	electrostatic forces, electromagnetic forces, Scaling in fluid mechanics,						
	Scaling in heat transfer						
	Unit 3: Microsystems Design and Packaging (8 Hrs)						
	Microsystem Design: Introduction, Design considerations, Process design,						
	Mechanical design, Microsystems packaging, Essential packaging						
	technologies, Fluid flow in nanoscale						
	Materials for MEMS and Microsystems, Fabrication techniques: Wafer						
	selection, Photolithography, Ion implantation, Diffusion, Oxidation, Wet and						
	Dry etching, CVD, PVD, RIE, Film deposition, Epitaxy Micromachining:						
	Bulk micromachining, Surface micromachining, Comparison of Bulk and						
	Surface micromachinings, LIGA and UE-LIGA processes, Lift-off techniques,						
	Mechanical design						
	Unit 5: MEMS Switches and Applications(9 Hrs)Data in the second						
	Fabrication of MEMS switches: capacitive switch, DC contact series switch,						
	Integration and biasing issues of MEMS switches, Design of CPW MEMS						
	Shunt Capacitive Switches, Single-Pole Multiple-Throw Switches, Double-						
	Pole Double-Throw switches, Inductive Matching of Shunt Capacitive						
	Switches, Inductively Resonant High-Isolation X-Band Capacitive Shunt						
	Switches, Switch parameters- Basics of switching, Mechanical RF switches,						
	Electronic switches for RF and microwave applications						
Text books	Textbooks:						
and							
Reference	1. Tai-Ran Hsu, "MEMS and Microsystems: Design and Manufacture,"						
books	Tata McGraw Hill, 2002.2. Gabriel M. Rebeiz, "RF MEMS Theory, Design, and Technology,"						
	2. Gabriel M. Rebeiz, "RF MEMS Theory, Design, and Technology," Wiley India Pvt Ltd.						
	3. Marc J. Madou, "Fundamentals of Microfabrication," CRC Press, 2nd						
	edition, 2002.						
	References:						
	1. Stephen D. Senturia, "Microsystem Design," Springer International						
	Edition, 2010.						
	2. Maluf, M., "An Introduction to Microelectromechanical Systems						
	Engineering," Artech House, Boston, 2000. 3. Mohamed Gad-el-Hak, "The MEMS Handbook," CRC Press, 2002.						
	4. Chang Liu, "Foundations of MEMS," 2 nd Edition, Pearson						
	Publication.						
E-resources	1. https://nptel.ac.in/courses/117105082/4						
and other	2. https://ocw.mit.edu/courses/electrical-engineering-and-computer-						
digital	science/6- 777j-design-and-fabrication-of-microelectromechanical-						
material	devices-spring- 2007/lecture-notes/						
	3. https://www.edx.org/course/micro-nanofabrication-mems-epflx-memsx- 0						

24ECVE505A: EMBEDDED SYSTEM DESIGN AND ARCHITECTURE

Course Category:	Program Elective -II	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	Computer Architecture	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course	Upon successful completion of the course, the student will be able to:					
outcomes	CO1	CO1 Know the embedded systems models, standards, block diagrams, a the von Neumann model. [K3].				
	CO2	instruction-le	and implemen vel parallelisi in embedded sy	m techniques		
	CO3	Understand th	ne processor ha	rdware, and tec	chniques for as	sessing and
	CO4		dware compon gh examples li		•	ith practical
	CO5		concepts and			
			stems with a language in er	-		-
Contribution		PO1	PO2	PO3	PO4	PO5
of Course Outcomes	CO1	3		2		1
towards achievement	CO2	2		1		1
of Program Outcomes	CO3	3	1	2	2	2
(1 – Low, 2 -	CO4	3	2	2	1	2
Medium, 3 – High)	CO5				2	3
Course Content	Unit 1: Introduction To Embedded Systems(9 Hrs)Embedded system model, Embedded standards, Block diagrams, Powering the hardware, Embedded board using von Neuman model.(9 Hrs)Unit 2: Introduction To Embedded Processors(9 Hrs)ISA architecture models, Application specific ISA models, General purpose ISA models, Instruction level parallelism(9 Hrs)Unit 3: Processor Hardware(9 Hrs)Internal processor design: ALU , Registers, Control unit, Clock , On chip memory, Processor I/O , Interrupts ,Processor buses, Processor performanceUnit 4: Support Hardware(9 Hrs)					

	Board memory: ROM , RAM , Cache, Auxiliary memory, Memory management ,Memory performance, Board buses: arbitration and timing, PCI bus example, Integrating bus with Components , Bus performance Unit 5: Software (9 Hrs) Middleware And Applications: PPP, IP Middleware, UDP, Java. Application Layer: FTP Client, SMTP, HTTP, Server And Client.
Text books and Reference books	 Textbooks: Tammy Noergard, "Embedded system architecture", Elsevier, 2022. References: Embedded System Design - Frank Vahid, Tony Givargis, John Wiley, 2021. An Embedded Software Primer - David E. Simon, Pearson Education, 2020. The Art of Designing Embedded Systems, Jack Ganssle, Newnes, 2019.
E-resources and other digital material	 <u>http://nptel.ac.in/courses/108102045/</u> <u>https://www.coursera.org/learn/embedded-software-hardware</u> <u>https://www.udemy.com/course/introduction-to-embedded-systems-arduino/?couponCode=LETSLEARNNOWPP</u> <u>https://www.coursera.org/learn/real-time-embedded-systems-concepts-practices</u> <u>https://www.coursera.org/learn/m2m-iot-interface-design-embedded-systems</u> <u>https://www.udemy.com/course/embedded-systems-bare-metal-programming/?couponCode=LETSLEARNNOWPP</u>

24ECVE505B: EMBEDDED C PROGRAMMING& PERIPHERAL INTERFACING

Course Category:	Program Elective -II	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	Programming in C, Digital Electronics, Microprocessors and Microcontrollers.	Semester end Evaluation:	40 60 100

Course	Upon	Upon successful completion of the course, the student will be able to:				
outcomes	CO1		Understand and analyze the design aspects, Architecture, and instruction set associated with ARM processors [K2]			
	CO2	•	SPIO Pins, Inter [K4]	rrupt handling,	and Timers cor	ncepts in task
	CO3	Apply the con	ncepts of UAR	Γ, ADC, and D	AC to Peripher	als [K3]
	CO4	Design and ir	nplementation	of embedded s	ystem serial pro	otocols [K3]
	CO5	Understand a	and implement	fixed-point an	nd floating-po	int DSP and
		apply skills in	n practical appl	ications such a	s smart home s	ystems [K6]
Contribution		PO1	PO2	PO3	PO4	PO5
of Course	CO1			1	3	2
Outcomes					-	
towards achievement	CO2	2		2	3	3
of Program	CO3	3		3	3	3
Outcomes	CO4	3		3	3	3
(1 – Low, 2 -	CO5	3		3	3	3
Medium, 3 –	005	5		5	3	5
High)						
Course	Unit	Unit 1: Embedded System Introduction & ARM Instruction set				
Content	Archi	itecture				(9 Hrs)
		Definition of Embedded Systems, Real life examples of embedded systems,				
		Basics of Developing for Embedded Systems, ARM Cortex-M Organization,				
		Arithmetic, Logical and Shift instructions, Data Movement Instructions, Branch instructions and Program Status register, Bitwise logic operations,				
			sion, Data Con	-	-	-
	-			-	•	
	Unit	nditional execution, Control structures, Subroutines, 64-bit data processing. hit 2: Interrupts & GPIO's (9 Hrs)				
			rupts, Interrupt		-	
		· · ·	and Unstackin	•	-	
	(NVI	C), Interrupt	Priority, GPIC	D Input Mode	es, GPIO Ou	tput Modes,

·	T					
	Memory-mapped I/O, Push button, Programming exercises on GPIO and Push-button, Clock Configuration, Timer Organization, and Counting Modes					
	Timer Update Events, PWM Registers, Configuration and initialization of PWM block, Programming exercises on the selection of clock source, Timer's concept, and PWM					
	Unit 3: UART, ADC/DAC & Interfacing (9 Hrs)					
	UART Block, UART Registers, UART baud rate calculation, Configuration and initialization of UART, ADC & DAC registers, pin configuration, ADC modes, Configuring ADC and DAC module, Programming exercises on ADC and DAC, DC motor, Keypad, LCD, and Seven segment display interfacing with ARM Cortex-M3 Microcontroller.					
	Unit 4: I ² C and SPI (8 Hrs)					
	I^2C operating modes, Configuration of I^2C , Interface a sensor using I^2C protocol, SPI Modes, Master operation, Slave operation, Configuration of SPI					
	Unit 5: Digital Signal Processing & Case Study (11 Hrs)					
	Fixed-point and Floating-point DSP, Fixed-point Data Types in DSP					
	Arithmetic Instructions: Parallel 8-bit Add and Subtract, Parallel 16-bit Add					
	and Subtract & 32-bit Add and Subtract, Add and Subtract Halfwords with					
	Exchange, 16-bit and 32-bit Multiplication					
	Case Study: Smart Home-Smart Door Locks and Interface a temperature sensor with an I ² C Module to measure the room temperature					
Text books	Textbooks:					
and	1. Dr. Yifeng Zhu "Embedded Systems with ARM Cortex-M					
Reference	Microcontrollers in Assembly and C" Third edition, 2018					
books	References: 1. Ariel Lutenberg, Pablo Gomez, Eric Pernia "A Beginner's Guide to					
	Designing Embedded System Applications on Arm Cortex-M					
	Microcontrollers"					
	2. Qing Li, Caroline Yao "Real-time concepts for Embedded Systems"					
	CMP books.					
E-resources	a. <u>www.digi.com/blog/post/examples-of-embedded-systems</u>					
and other	b. Embeddedinventor.com/embedded-timers-their-types-and-applications/					
digital material	 c. Tutorialspoint.com/embedded_systems/es_interrupts.html d. https://www.digikey.in/en/blog/adc-dac-tutorial-blog 					
material	e. https://www.digikey.in/en/olog/adc-dac-tutorial-olog e. https://exploreembedded.com/wiki/LPC1768: ADC Programming					
	f. https://www.keil.com/dd/docs/datashts/philips/lpc17xx_um.pdf					
	g. https://www.nxp.com/docs/en/datasheet/LPC1769 68 67 66 65 64 63.					
	pdf					
	h. https:// <u>www.mdpi.com/2079-9292/12/20/4236</u>					
	i. https://www.wiley.com/en-					
	us/Arithmetic+Circuits+for+DSP+Applications-p-9781119206798					

24ECVE505C: ELECTRONICS DESIGN: SENSOR AND ACTUATORS

Course Category:	Program Elective -II	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	Basic knowledge of	Continuous Evaluation:	40
	electronics,	Semester end Evaluation:	60
	Understanding of	Total Marks:	100
	fundamental physics		

Course	Upon	Upon successful completion of the course, the student will be able to:					
outcomes	CO1	Understand th	Understand the working principles of different sensors. [K2].				
	CO2	2	Analyze the working of different optical, pressure and humidity sensors and actuators. [K4].				
	CO3	Assess the chapplications.		e Interfacing d	ifferent sensor	rs for diverse	
	CO4	Understand th applications.		nciples of diffe	rent smart sens	sors and their	
	CO5	Understand th	ne fabrication a	nd working of	MEMS. [K2].		
Contribution		PO1	PO2	PO3	PO4	PO5	
of Course Outcomes	CO1	2					
towards achievement	CO2	2					
of Program Outcomes	CO3	2					
	CO4	2		1			
(1 – Low, 2 - Medium, 3 – High)	CO5	2		2			
Course	Unit	1: Sensors	I	I	I	(10 Hrs)	
Content	Consi Select Induc Conta Encoo Unit 2 Stepp Optic Presso Senso Humi Humi	Unit 1: Sensors(10 Hrs)Sensor Fundamentals: Basic Sensor Technology, Sensor Systems, Application Considerations: Sensor Characteristics ,System Characteristics ,Instrument Selection ,Data Acquisition and Readout Installation, Capacitive sensor, Inductive sensors, Selecting and Specifying Capacitive and Inductive Sensors, Contact and Non-contact Position Sensors, String Potentiometer and String Encoder Engineering Guide, Linear and Rotary Position and Motion Sensors Unit 2: Actuators, Optical, Pressure and Humidity Sensors (10 Hrs) Stepper Motors, Voice-Coil actuators, Fluid actuators Optical and Radiation Sensors: Photosensors, Thermal Infrared Detectors Pressure Sensors: Piezoresistive Pressure Sensing, Piezoelectric Pressure Sensors Humidity Sensors: Sensor Types and Technologies, Selecting and Specifying Humidity Sensors, Applicable Standards and Interfacing and Design Information.					

	Unit 2. Interfacing Congorg and Actuators (0 Harr)
	Unit 3: Interfacing Sensors and Actuators (9 Hrs) General Requirements for Interfacing Sensors and Actuators, Signal Level,
	Impedance, Response and Frequency, Input Signal Conditioning, Offset,
	Scaling, Isolation, Loading, Output Signals, Errors-Resolution Errors,
	Computation Errors, Sampling and Quantization Errors and Conversion
	Errors, Sensors and Actuator networks
	Applications-Environmental monitoring, health care, logistics, transportation,
	Network Organization, Energy, Communication
	Unit 4: Smart Sensor Technologies (8 Hrs)
	Smart Sensor basics, Micromachining: Bulk Micromachining, Wafer bonding, Silicon-on-Silicon Bonding, Silicon-on-Glass (Anodic) Bonding, Silicon Fusion Bonding, Wafer Bonding for More Complex Structures and Adding ICs, Combinations of Surface and Bulk Micromachining
	LIGA Process, Dry-Etching Processes
	Unit 5: MEMS (8 Hrs)
	Introduction, Micromachined Actuators, Microvalves, Micromotors, Micropumps, Microdynamometers, Microsteam Engines, Actuators in Other Semiconductor Materials, Other Micromachined Structures, Cooling Channels, Microoptics, Microgrippers, Microprobes, Micromirrors, Heating Elements, Thermionic Emitters, Field Emission Displays, Unfoldable
	Microelements, Micronozzles, Interconnects for Stacked Wafers
Text books	Textbooks:
and	1. Sensor Technology hand book by Jon S. Wilson, Elsevier publications
Reference books	2. Understanding Smart Sensors, Second Edition by Randy Frank.
	References:
	1. Patranabis D, Sensors and Transducers, Tata McGraw Hill, Seventh
	Edition, 2003.
	2. Ian R Sinclair, Sensors and Transducers, Newnes publishers, Third Edition, 2001.
	3. Handbook of Modern Sensors Physics, Designs, and Applications, Jacob Fraden, Third Edition, Springer publications
	 4. Sensors, actuators, and their interfaces : A multidisciplinary introduction by Nathan Ida , SciTech Publishing, Edison, NJ, ©2014 5. Sensors and Actuators by Francisco Andre Correa Alegria, June 2021.
E-resources	1. https://www.celeramotion.com/inductive-sensors/support/technical-
and other	papers/inductive-and-capacitive-position-sensors/
_	

digital	2.	https://www.machinedesign.com/automation-
material		iiot/sensors/article/21831577/baumer-electric-types-of-proximity-
		sensors-from-inductive-to-ultrasonic
	3.	https://www.sciencedirect.com/topics/engineering/optical-sensors
	4.	https://ptolemy.berkeley.edu/projects/chess/eecs124/lectures/Interfac
		eToSensorsActuators.pdf
	5.	https://www.elprocus.com/smart-sensor/
	6.	https://www.inseto.co.uk/wafer-bonding-methods/
		-

24ECVE505D: INTERNET OF THINGS FOR REAL TIME SYSTEMS

Course Category:	Program Elective -II	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	UG Embedded Systems	Continuous Evaluation:	40
	Semester end Evaluation:		60
		Total Marks:	100

Upon successful completion of the course, the student will be able to:					
Identify and explain IoT protocols, enabling technologies, and communication models. [K2].					
Design and implement IoT systems using a structured methodology [K3].					
programming skill	programming skills in Pyth	hon. [K3]			
IoT applications a	IoT applications and proje	ects using Raspberry P	i. [K3]		
eal-world case stu	real-world case studies rep	presenting diverse IoT	applications		
PO2	PO2 PO	O3 PO4	PO5		
		2			
		2			
		2 2			
		2 3			
		3	3		
Unit 1: Introduction to IoT(9 Hrs)Introduction: Definition & Characteristics of IoT, Physical Design of IoT, Things in IoT, IoT Protocols, Logical Design of IoT, IoT Functional Blocks, IoT Communication Models, IoT Communication API's, IoT Enabling Technologies, Wireless Sensor Networks, Cloud Computing, Big Data Analytics, Communication Protocols, Embedded Systems Domain Specific IoTs: Introduction, Home Automation, Cities, Environment, Energy, Retail, Logistics, Agriculture, Industry, Health & Lifestyle. Unit 2: IoT and M2M(9 Hrs)IoT and M2M(9 Hrs)IoT and M2M- IoT and M2M- Software Defined Networking, Network Function Virtualization.Nethodology- Introduction, IoT Design Methodology, Case Study on IoT System for Weather Monitoring					
	2	ase Study on loT System			

	Introduction to Python, Python Data types & Data Structures, Control flow,							
	functions, Modules, Packages, File Input/output, Date/Time Operations,							
	Classes.							
	Unit 4: loT Physical Devices & Endpoints(9 Hrs)loT Physical Devices & Endpoints - Basic building blocks of a loT Device,Exemplary Device: Raspberry PI, Raspberry PI Interfaces, serial, SPI, I2C,Programming Raspberry Pi with Python, Controlling LED with Raspberry Pi,Interfacing an LED and Switch with Raspberry Pi, Interfacing LDR with							
	Raspberry Pi.							
	Unit 5: Case Studies illustrating IoT Design (9 Hrs) Introduction, Home Automation, Smart lighting, home intrusion detection, Cities, smart parking, Environment, weather monitoring system, weather reporting bot, air pollution monitoring, forest fire detection, Agriculture, smart irrigation.							
Text books	Textbooks:							
and	1. Arshdeep Bahga, Vijay Madisetti, Internet of Things A Hands-on							
Reference	Approach, Universities press (India) Pvt. Ltd, 2023.							
books	References: 1. Rajkumar Buyya, Amir Vahid Dastjerdi, and Syed Shahrestani,							
	"Internet of Things: Principles and Paradigms", Morgan Kaufmann							
	Publishers, 2016.							
	2. Maciej Kranz, "Building the Internet of Things: Implement New							
	Business Models, Disrupt Competitors, Transform Your Industry",							
	Jhon Wiley & Sons publishers, 2016.							
	 Brian Russell and Drew Van Duren, "Practical Internet of Things 							
	Security", PACKT publishers, 2016.							
E-resources	a. https://www.i-scoop.eu/internet-of-things-guide/							
and other	b. https://www.postscapes.com/internet-of-things-protocols/							
digital	c. https://www.ibm.com/cloud/learn/internet-of-things							
material	d. https://www.link-labs.com/blog/iot-vs-m2m							
111411141	e. <u>https://www.sdxcentral.com/sdn/definitions/what-the-definition-of-</u>							
	software-defined-networking-sdn/							
	f. https://www.networkworld.com/article/3238446/what-is-nfv-network-							
	functions-virtualization-explained.html							
	g. <u>https://www.learnpython.org/en/Control Flow</u>							
	h. <u>https://realpython.com/python3-object-oriented-programming/</u>							
	i. <u>https://www.raspberrypi.org/documentation/usage/python/</u>							
	j. <u>https://www.smarthome.com.au/smarthome-case-studies</u>							
	k. https://www.smartcitiesworld.net/news/news/smart-city-case-studies-							
	<u>4449</u>							
	1. <u>https://www.hackster.io/projects/environmental-monitoring</u>							
	m. <u>https://www.iotforall.com/smart-agriculture-iot</u>							

24MTUC501: RESEARCH METHODOLOGY AND IPR

Course Category:	Mandatory Learning	Credits:	0
	Course		
Course Type:	Theory	Lecture - Tutorial -Practice:	2-0-0
Prerequisites:	-	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course	Upon	successful con	pletion of the	course, the stud	dent will be ab	e to:		
outcomes	CO1	Demonstrate proficiency in formulating research problems, applying scientific methods, and understanding the significance of research methodology in academic and professional settings. [K2]						
	CO2	research meth	Achieve proficiency in critically reviewing literature, enhancing research methodologies, and designing effective research studies that contribute to knowledge broadening and contextual understanding.					
	CO3	measurement	Gain proficiency in designing reliable sampling strategies, applying measurement scales, and executing data collection methods to minimize errors and enhance research validity.[K2]					
	CO4	• 1	Conduct hypothesis tests, interpret test statistics, and utilize data analysis methods to enhance research validity. [K2]					
	CO5	Interpret research results, write impactful reports, and apply knowledge of intellectual property rights to research practices. [K2]						
Contribution		PO1	PO4	PO5				
of Course Outcomes	CO1	2						
towards achievement	CO2					2		
of Program	CO3				2			
Outcomes	CO4		1	2				
(1 – Low, 2 -								
Medium, 3 –	CO5			2				
High)								
Course	Unit	1: Research M	ethodology: an	nd Research P	roblem (5 H	Irs)		
Content		T / 1 /				01 ::		
	•			Methodolog	• •	•		
	•	Motivation, Approaches, Significance, and Scientific Methods. Research Process: Steps, Criteria of Good Research, and Common Problems Encountered by Researchers in India.						

 Defining the Research Problem: Selecting an Techniques, and Illustration. Unit 2: Literature Review and Research Design Reviewing the Literature: Importance, Met 	
Unit 2: Literature Review and Research Design	(5 Hrs)
	(5 Hrs)
Reviewing the Literature: Importance, Met	(0 1115)
 Knowledge Broadening, and Contextual Find Research Design: Meaning, Need, Feature Concepts, Basic Principles, and Experimental 	lings. res of a Good Design, l Designs.
Unit 3: Sampling Design , Data Collection, ICT T Research: (5 Hrs)	Sools and Techniques in
 Design of Sampling: Introduction, Sample Desampling Errors, Sample vs. Census Survey. Measurement and Scaling: Qualitative a Measurement Scales, Goodness, and Sources Data Collection: Experimental and Surveys, Data Collection, Case Study Method. Software for Reference Management (Zoter Plagiarism, Research search Engines Unit 4: Hypothesis Testing and Data Analysis(5 Herodet) 	and Quantitative Data, of Error. , Primary and Secondary ro/ Mendeley), detecting
 Testing of Hypotheses: Concepts, Hypothesis Critical Region, Value and Decision Rule, Pro- Data Analysis: Techniques and Tools for Ana Unit 5: Interpretation, Report Writing, and Intell Interpretation and Report Writing: Meaning, and significance of report writing. Intellectual Property: Concept, system in India complied regime, Patents Act, Trade Ma Geographical Indications, Copyright Act, Models, WTO, Paris Convention, Nationa Priority, Common Rules, PCT, and TRIPS Approximately 	rocedure. alyzing Collected Data. lectual Property (5 Hrs) , techniques, precautions, a, development of TRIPS fark Act, Designs Act, Trade Secrets, Utility al Treatment, Right of
Text books Textbooks:	0
and 1. Research methodology: Methods and Tec	chniques, C.R. Kothari,
AndReferenceGaurav Garg, New Age International, 4th Edit	-
2 Research Methodology a step by step guid	
books 2. Research Methodology a step-by-step gate Kumar, SAGE Publications Ltd.,3rd Edition,	
3. Study Material, Professional Programme Inte	
Law and Practice, The Institute of Compa	my Secretaries of India,
Statutory Body under an Act of Parliament, S	September 2013.
References:	
1. An introduction to Research Methodology,	Garg B.L et al ,RBSA
Publishers 2002	
2. An Introduction to Multivariate Statistical A Wiley 3rd Edition,	Analysis Anderson T.W,
3. Research Methodology, Sinha, S.C, Dhiman,	EssEss Publications2002
4. Research Methods: the concise knowledge bas	
Publishing ,2005 5. How to Write and Publish a Scientific Pape University Press 1992	er, Day R.A, Cambridge

r								
	6. Conducting Research Literature Reviews: From the Internet to Paper,							
	Fink A, Sage Publications, 2009							
	7. Proposal Writing, Coley S.M. Scheinberg, C.A, Sage Publications,							
	1990							
	8. Intellectual Property Rights in the Global Economy, Keith Eugene							
	Maskus, Institute for International Economics							
E-resources	1. https://www.techtarget.com/whatis/definition/scientific-method							
and other	2. <u>https://www.geophysik.uni-</u>							
digital	muenchen.de/~valerian/Scientific_Working/SRMTunit2.pdf							
material	3. https://hmhub.in/3rd-4th-sem-research-methodology-notes/criteria-of-							
	good-research/							
	4. https://researcher.life/blog/article/what-is-a-research-problem-types-and-							
	examples/							
	5. <u>https://www.questionpro.com/blog/data-collection-methods/</u>							
	6. <u>https://southcampus.uok.edu.in/Files/Link/DownloadLink/RM%20U2%</u>							
	<u>20P2.pdf</u>							
	7. <u>https://www.studysmarter.co.uk/explanations/psychology/cognition/form</u>							
	ulation-of-hypothesis							
	8. <u>https://www.aimlaywriting.com/significance-of-research-report-writing/</u>							
	9. https://www.lexology.com/library/detail.aspx?g=7045cf52-4a2c-465f-							
	980b-b5af034e2064							
	10. https://www.trade.gov/country-commercial-guides/india-protecting-							
	intellectual-property							
	monorial property							

24ECVE581: DIGITAL SYSTEM DESIGN LAB

Course Category:	Laboratory-I	Credits:	1.5
Course Type:	Laboratory	Lecture - Tutorial -Practice:	0-0-3
Prerequisites:	Digital Logic Design	Continuous Evaluation:	60
		Semester end Evaluation:	40
		Total Marks:	100

Course	Upon	successful con	successful completion of the course, the student will be able to:						
outcomes	CO1	Get acquainte	Get acquainted with programmable logic design flow.						
	CO2	Implement de	Implement designed digital circuits using FPGA.						
	CO3	Synthesize the	e designed circ	uits using CAI	D tools				
Contribution		PO1	PO2	PO3	PO4	PO5			
of Course Outcomes	CO1		1	2	3	2			
towards achievement	CO2	2	1		3	2			
of Program Outcomes									
(1 – Low, 2 -	CO3		1 3 2						
Medium, 3 – High)									
Course	List o	of Experiment	<u>.</u> S						
Content	1.			g module for a 4	1-bit binary-to-	BCD (Binary			
			nal) converter.						
	2.				ystem Verilog.				
	3.		t and right shi		a 4-bit shift rea	gister and			
	4.	-	•		System Verilo	a that			
			equence: 0, 1, 2			,g that			
	5.				nent a synchro	nous counter			
		that counts fr	rom 0 to 15 and	then resets.	-				
	6.	Implement a multiplier.	System Verilog	g program to d	efine a 3x3 ma	trix			
	7.	Write a Syste		dule to generat	e a PWM signa	ıl with			
	0	variable duty	•	momorymod	ula in System V	Iorilog			
	8. 9.		Verify Full ad	•	ule in System V	r ennog.			
	10.		Verify D-Flip						
	11.		• •	- Г					
	12.		Verify Binary	to Gray Conv	erter				

24ECVE582: EMBEDDED SYSTEMS DESIGN LAB

Course Category:	Laboratory-II	Credits:	1.5
Course Type:	Laboratory	Lecture - Tutorial -Practice:	0-0-3
Prerequisites:	Computer Architecture	Continuous Evaluation:	60
		Semester end Evaluation:	40
		Total Marks:	100

Course	Upon successful completion of the course, the student will be able to:							
outcomes	CO1	CO1 Design and execute the different concepts for embedded system using ARM processor.						
Contribution		PO1	PO2	PO3	PO4	PO5		
of Course								
Outcomes								
towards								
achievement								
of Program	CO1				2			
Outcomes								
(1 – Low, 2 -								
Medium, 3 –								
High)								
Course	Expe	eriments using	ARM Cortex-	-M Microcont	troller (NUCL	EO board -		
Content	F4292	ZI):						
	Program to configure and control General Purpose Input / Output (GPIO) port							
	pins.							
	-	Dragram to day	nonstrata Saria	1 aammuniaati	on Tronsmissi	on from Vit and		
		-				on from Kit and		
		-	-	I Port on IDE e	environment use	e debug terminal		
		to trace the pro	0	1.1		Timer		
		Program to den feature on IDE		delay program	n using built in	Timer / Counter		
		Program to den		nle interrunt h	andler and setti	ing up a timer		
		•		• •		ers LCD display		
		and verify the r		-		ers LCD display		
		Program to den	-					
		U U		•	ive of introduct	ing the practical		
		application of t	0	•		0 1		
		1 1		-	1	or the purpose of		
		storing event lo				or the purpose of		
		•	•	•		systems using		
						itoring pertinent		
						hrough the other		
		system.	in one system	and facilitatili		in ough the other		
		-	smart home sy	stem hv enabli	ng it to host a w	veb page through		
			•	•	-	rmation using a		
		smartphone or	• •	mowing users		imation using a		
		-	I U.					
	10.	Project						

24ECVE591: CAPSTONE PROJECT-1

Course Category:	Program Core-I	Credits:	1
Course Type:	Project	Lecture - Tutorial -Practice:	0-0-2
Prerequisites:	Core courses in the	Continuous Evaluation:	60
	M.Tech - VLSI Design	Semester end Evaluation:	40
	and Embedded Systems	Total Marks:	100
	program, including		
	courses in digital design,		
	embedded systems, and		
	relevant electives.		

Course	Upon successful completion of the course, the student will be able to:						
outcomes	CO1						
	CO2	and ethics.CO3Generate possible alternative solutions to the chosen problem, compare, analyze them and derive performance metrics of the result.					
	CO3						
	CO4						
Contribution		PO1	PO2	PO3	PO4	PO5	
of Course							
Outcomes	CO1	2			1	1	
towards achievement	CO2	1		1	1	1	
of Program	CO3	3		2	3	1	
Outcomes	CO4		3	2		1	
(1 – Low, 2 - Medium, 3 – High)							
Course	Week 1-2: Project Topic Selection						
Content	 Introduction to the course and capstone project expectations Brainstorm project ideas Form project teams Choose a project topic and define initial objectives Week 3-5: Project Proposal Develop a project proposal that includes a clear problem statement Outline the methodology and approach to be used 						

	Create a preliminary project timeline							
	Submit project proposals for approval							
	Week 6-8: Literature Review							
	 Conduct a literature review of relevant research and existing solutions Identify key papers, articles, and resources Document gaps in current knowledge and technologies Week 9-11: Project Planning Refine project scope and objectives based on literature review Develop a detailed project plan with tasks, milestones, and deadlines Allocate resources and budget for the project 							
	Week 12-14: Progress Report							
	 Prepare a progress report summarizing work completed to date Discuss challenges and potential solutions Review and adjust the project plan if necessary 							
	Week 15-16: Midterm Presentation							
	• Present the project proposal, literature review, and project plan to faculty and peers							
	• Receive feedback and suggestions for the next phase (Capstone Project-2)							
E-resources and other	Recommended textbooks and research papers related to the project topic							
digital material	 Access to relevant software and hardware tools Project management software (e.g., Microsoft Project or equivalent) 							

SEMESTER II

24ECVES00: Hardward Softward Codesign					
Course Category:	Programme Core - IV	Credits:	3		
Course Type:	Integrated	Lecture - Tutorial -Practice:	2-0-2		
Prerequisites:	Embedded Systems	Continuous Evaluation:	40		
		Semester end Evaluation:	60		
		Total Marks:	100		

24ECVE506: Hardware/Software Codesign

Course Outcomes	Upon	successful con	npletion of the	course, the stud	dent will be abl	e to:			
Outcomes	CO1	CO1 Demonstrate an understanding of hardware/software co-design models and methodologies.							
	CO2	-	apply hardware oning and distr	•	-	s for efficient			
	CO3		imulate hardw rchitecture spe			l emulations,			
	CO4		d design arch nd mixed system						
	CO5	Utilize moder	m compilation	technologies to	optimize embe	dded systems			
Contribution of Course		PO1	PO2	PO3	PO4	PO5			
Outcomes towards	CO1	2		3	3	2			
achievement of Program	CO2	2		3	3	2			
Outcomes (1 – Low, 2-	CO3	2		2	2				
Medium, 3 – High)	CO4	2		3		2			
8 /	CO5	2		2	3				
Course						(9Hrs)			
Content	Co-	-	ls, Architectu	res, Language	es, A Generi	c Co-design			
	UNIT					(9Hrs)			
	Hardware/ Software Co- Synthesis Algorithms Hardware software synthesis algorithms: hardware – software partitioning distributed system co-synthesis.								
	UNIT	III:	•			(9Hrs)			
	Prototyping and Emulation Prototyping and emulation techniques, prototyping and emulati environments, future developments in emulation and prototyping architectu specialization techniques, system communication infrastructure.								

	UNIT IV: (9Hrs)					
	(9 Hrs) Target Architectures Architecture Specialization techniques, System Communication infrastructure, Target Architecture and Application System classes, Architecture for control dominated systems (8051-Architectures for High performance control), Architecture for Data dominated systems (ADSP21060, TMS320C60), Mixed Systems. UNIT V: (9Hrs) Compilation Techniques and Tools for Embedded Processor Architectures Modern embedded architectures, embedded software development needs, compilation technologies, practical consideration in a compiler development environment.					
Text books and Reference books	 Text Books: 1. Hardware / Software Co- Design Principles and Practice – Jorgen Staunstrup, Wayne Wolf – 2009, Springer. Reference Books: 1. Hardware / Software Co- Design - Giovanni De Micheli, Mariagiovanna Sami, 2002, Kluwer Academic Publishers. 2. A Practical Introduction to Hardware/Software Co-design -Patrick R. Schaumont - 2010 – Springer Publications. 					
E-resources and other digital material	 <u>https://www.coursera.org/learn/computer-hardware-software</u> <u>https://dspace.mit.edu/handle/1721.1/84891</u> 					

24ECVE507: Real Time Operating Systems

Course Category:	Program Core - V	Credits:	3
Course Type	Theory	Lecture-Tutorial-Practice	3-0-0
Prerequisites:	Embedded Systems	Continuous Evaluation:	40
	concepts and Operating	Semester end Evaluation:	60
	System	Total Marks:	100

	Upon	successful con	npletion of the	course, the stuc	lent will be abl	e to:			
	CO1	Explain the fundamental principles of real-time operating systems, including task management, scheduling, and the unique characteristics that differentiate RTOS from general-purpose operating systems							
	CO2	as semaphore	Apply various synchronization and communication mechanisms, such as semaphores, message queues, and condition variables, to effectively manage task coordination in real-time systems						
Course Outcomes	CO3	implement t	Analyze the role of exceptions, interrupts, and timers in RTOS and implement these components to support responsive, real-time functionality in embedded applications						
	CO4	utilizing sync	chronization m	bsystems in re ethods and ha system operation	ndling priority				
	CO5	resource class	Identify and address common design challenges in RTOS, including resource classification, deadlocks, and priority inversion, to enhance the stability and performance of real-time applications						
Contribution of Course		PO1	PO2	PO 3	PO 4	PO5			
Outcomes towards	CO1	2	1	3	2	2			
achievement of Program	CO2	2	1	3	3	2			
Outcomes (1 – Low, 2 -	CO3	3	1	3	3	2			
Medium, 3 – High)	CO4	3	1	3	3	3			
	CO5	3	1	3	3	3			
Course Content	Intro sched Task Task Comm UNIT	UNIT I:(9 Hrs)Introduction to Real-Time Operating Systems -Defining an RTOS, The scheduler, Kernel objects and services, Key characteristics of an RTOS.Task management:Defining a Task, Task States and Scheduling, Typical Task Operations, Typical Task Structure. Introduction to Synchronization, Communication, and Concurrency in real-time environments.UNIT II:(9 Hrs)Semaphores -Definition, typical operations, and usage in RTOS.							

	Message Queues -Definition, states, content, storage, operations, and typical					
	use. Pipes -Introduction to Pipes, Event Registers, Signals, and Condition Variables as tools for managing synchronization and communication in real-time					
	applications.					
	UNIT III: (9 Hrs) Exceptions and Interrupts -Definition, applications, and deeper exploration of their nature and management in RTOS, including handling spurious					
	interrupts. Timer and Timer Services - Real-time clocks, system clocks, programmable interval timers, and timer interrupt service routines essential for real-time					
	applications. UNIT – IV: (9 Hrs)					
	I/O Subsystems -I/O concepts and subsystems in RTOS					
	Synchronization and Communication -Resource synchronization methods, critical sections, and common design patterns in RTOS.					
	Priority: Introduction to Priority Inversion and methods to address it in real- time operating systems.					
	UNIT – V: (9 Hrs)					
	Design Issues: Analyzing and managing common design issues in real-time systems, including resource classification, deadlocks, and priority inversion. Methods to address and mitigate these issues within the context of RTOS to ensure efficient system functionality and responsiveness.					
Text books and	Text Books: 1. Qing Li, Caroline Yao (2023), "Real-Time Concepts for Embedded Sustaines" CMB Basilis					
Reference books	Systems", CMP Books Reference Books:					
DUOKS	 Albert Cheng, (2022), "Real-Time Systems: Scheduling, Analysi Verification", Wiley Interscience. 					
	 Hermann Kopetz, (2019), "Real-Time Systems: Design Principle Distributed Embedded Applications", Kluwer. 					
	3. Insup Lee, Joseph Leung, and Sang Son, (2018) "Handbook of Real Systems", Chapman and Hall.					
	4. Krishna and Kang G Shin, (2022), "Real-Time Systems", McGraw Hill					
E-resources and other digital	 <u>https://nptel.ac.in/courses/106105036/</u> <u>https://nptel.ac.in/noc/individual_course.php?id=noc18-cs12</u> 					
material						

24ECVE508: Analog & Mixed Signal Design

Course Category	Program Core-VI	Credits	3
Course Type	Theory	Lecture-Tutorial-Practice	3-0-0
Prerequisite	CMOS VLSI Design	Continuous Evaluation:	40
-		Semester end Evaluation:	60
		Total Marks:	100

Course	Linon guos	ageful completi	on of the ear	uras the stude	nt will be ab	lata	
Course Outcomes	Upon successful completion of the course, the student will be able to:						
Outcomes	CO1 CO2						
	002				ers to me	et specific	
		performance r			4 1		
	CO3	Design feedb	ack ampli	tiers, Company	rators and	ADC's for	
		practical analo			cations.		
	CO4 Design switched-capacitor circuits.						
	CO5	Implement ad mixed-signal			for optimal	analog and	
Contribution of		PO1	PO2	PO3	PO4	PO5	
Course	CO1	2	102	3	101	100	
Outcomes	CO2		2	3			
towards	CO2 CO3	3		3			
achievement of	CO3	3		3			
Program							
Outcomes	CO5	3		3			
(1–Low,							
2-Medium,							
3 - High)							
Course	UNIT-I:					(9 Hrs)	
Content		a Amulifian	and Cu		ong Comm		
Content	0	age Amplifier					
		gate and source		-		ed cascode	
		Frequency resp	ponse, MOS	S current mirro	ors-sources.		
	UNIT-II:					(9 Hrs)	
	MOS Dif	ferential Amp	olifiers and	Operation	al Amplifie	rs - Single	
		differential op					
		Frequency resp					
	1 ·	1 / 1		1	1	- One-stage	
		nd Folded Case	code Op-A	mps and Prop	berties.		
	UNIT-III:					(9 Hrs)	
		Amplifiers -					
	Compara	tors and Anal	og-Digital	converters -	-Two stage,	Open-loop	
	comparato	rs, Parallel digi	tal-analog c	converters.	-	-	
	UNIT-IV:	e	J			(9 Hrs)	
		Switched-Capacitor circuits – Sampling switches, Switched-Capacitor					
	amplifiers, Switched-Capacitor integrator. UNIT-V: (9 Hrs)						
		Design – Gene	ral Lavou	t Considerat	ions Anal		
		s, Substrate Co		i Considerat	ions, Anar	Sg Layout	
Textbooks and	Text Book	/	aping.				
Reference		Razavi (2002).	"Design o	f Analog CM	OS Integrate	d Circuits"	
books	Tata-Mc G		, Design 0	i Allalog CM	US megiate		
DOOR2		Allen & D	ouglas Hol	herg (2002)	CMOS And	log Circuit	
		Oxford Universi		uerg (2002),	CIVIOS Alla	nog Circuit	
		stings (2004) T		nalog Lavout	Second Editi	on Pearson	
	Education.		ne An UI Al	laiog Layout,			
	Laucation.						

	Reference Books: 1. David A Johns & Ken Martin (2001), "Analog Integrated Circuit Design" John Wiley and Sons
E-resources	CMOS Analog VLSI Design by Prof. A.N. Chandorkar, Department of
and other	Electronics & Communication Engineering, IIT Bombay. For more details on
digital material	NPTEL visit <u>http://nptel.ac.in</u>

Course Category:	Programme Elective-III	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	
Prerequisites:	Devices and circuits	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

24ECVE509A: Low Power VLSI Design

Course Outcomes	Upon successful completion of the course, the student will be able to::							
	CO1	Apply different circuit techniques to manage the leakage currents						
	CO2	Comprehend	l and analyz	e various low	power add	er and multiplier architectures.		
	CO3	Understand ROM.	the architect	ural and circu	it level tech	nniques for attaining low power		
	CO4	Design and a	analyze the d	ifferent types	of low pow	ver SRAM and DRAM circuits.		
	CO5	Decide white designs.	ch level of	abstraction is	advantage	eous to implement low power		
Contributio n of Course		PO1	PO2	PO3	PO4	PO5		
Outcomes towards achievement	CO1	3	3	2	1	1		
of Program Outcomes (1 – Low, 2 - Medium, 3 –	CO2	3	3	2	1	2		
	CO3	3	3	3	1	2		
High)	CO4	3	3	3	1	2		
	CO5	2	2	2	1	2		
Course Content	UNIT I: (9 Hrs) Low power CMOS VLSI design - Introduction, sources of power dissipation, static power dissipation, active power dissipation. Circuit techniques for low power design - Introduction, designing for low-power, circuit techniques for leakage power reduction UNIT II: (9 Hrs) Low voltage low power adders - Introduction, standard adder cells, CMOS adder's architectures, low voltage low power design techniques, current mode adders. Low voltage low power multipliers - Introduction, overview of multiplication, types of multiplier architectures, Braun multiplier, booth multiplier, Wallace tree multiplier UNIT III: (9 Hrs) Low- Voltage Low Power Read-Only Memories - Introduction, types of ROM, basics physics of floating gate non-volatile devices, floating gate memories, basics of ROM, low power ROM Technology UNIT – IV: (9 Hrs)							

	Low voltage low power static RAM - Basics of SRAM, memory cell, precharge and equalization circuit, address transition detection, sense amplifier, output latch, low power SRAM technologies, Low voltage low power dynamic RAM - Types of DRAM, basics of DRAM, self-refresh circuit, half voltage generator, voltage down converter, future trends and developments of DRAM UNIT-V: (9 Hrs) Architectural Techniques for Low Power: Parameters effecting power dissipation, Variable frequency, Dynamic voltage Scaling, Dynamic Voltage and Frequency Scaling, Reduced VDD, Architectural clock gating, Power gating, Multi-voltage, Optimizing memory power. Low Power Implementation Techniques: Library Selection, Clock Gating, Timing Impact due to Clock gating, Gate-level power optimization techniques, Power Optimization for Sleep Mode
Textbooks and Reference books	 Textbooks: Kiat Seng Yeo, Kaushik Roy (2012)," Low Voltage, Low Power VLSI Subsystems", TATA McGraw-Hill. Soudris D, Piguet C and Goutis C, Designing CMOS Circuits for Low Power, Kluwer Academic Publishers, 2002. Reference Books: Yeo Rofail, Gohl (2009)," CMOS/BiCMOS ULSI Low Voltage, Low, Power", Pearson Education Asia 1st Indian reprint. Anantha P. Chandrakasan, Robert W. Brodersen, "Low Power Digital CMOS Design", Springer Science Jan M. Rabaey, Anantha P. Chandrakasan, Borivoje Nikolic, (2011) "Digital Integrated Circuits: a Design Perspective", PearsonEducation, 2nd Edition.
E-resources and other digital material	 <u>http://www.nptelvideos.com/course.php?id=422</u> <u>http://leda.elfak.ni.ac.rs/education/projektovanjeVLSI/predavanja/10%20Low%20Power%20Design%20in%20VLSI.pdf</u> <u>https://www.egr.msu.edu/classes/ece410/salem/files/s16/lectures/Ch2_S2_N.pdf</u>/

24EC	24ECVES09B: Semiconductor Packaging and Testing					
Course Category:	Programme Elective-III	Credits:	3			
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0			
Prerequisites:	IC Technology	Continuous Evaluation:	40			
		Semester end Evaluation:	60			
		Total Marks:	100			

Course	Upon	Upon successful completion of the course, the student will be able to:						
outcomes	CO1 Understand the various packaging types used in modern technology.							
	CO2	Eundamentals of the associated thermal speed signal and integrity						
	CO3	surmount tec	he different of hnology. Designer her frequency.					
	CO4	Explore CAD	tools for PCB	design and boa	ard assembly te	echniques		
	CO5		oncepts of Tes					
Contribution		PO1	PO2	PO3	PO4	PO5		
of Course		1	3	2	2	2		
Outcomes	CO1	_	-	_	_	_		
towards		2	3	2	1	2		
achievement	CO2	2	3	2	1	Ζ		
of Program Outcomes	CO3	2	3	1	2	2		
(1 - Low, 2 -	003			-				
Medium, 3 –	CO4	1	3	2	2	2		
High)	CO5	1	3	1	2	2		
Course	Unit	l: Microsysten	ns Packaging		L	(9Hrs)		
Course Content	Introd MEM Relate their Metal Unit 2 Electr Distri Desig Vario Unit 3 IC As Wire Single Chara Multi							
	2	n – in - packag		,	ntegrated, and e			
	Unit 4	4: PCB and su	riace mount to	ecnnology		(9Hrs)		

miconductor Packaging and Testing 24FCVF500R+ Sa

boards.Board Assembly: Surface Mount Technology, Thorough Hole technology, Process Control and Design Challenges. Thermal Considerations: Thermal management, Heat Transfer Fundamentals, Thermal Conductivity and Resistance, Conduction, Convection and Radiation, Importance of Cooling. Unit 5: Testing Technology and Reliability (9Hrs) Basic Concepts, Environmental Interactions. Thermal Mismatch and Fatigue- Failures-Thermo Mechanically Induced, Electrically Induced, Chemically Induced. Electrical Testing: System Level Electrical Testing, Interconnection tests, Active Circuit Testing, Design for Testability, Basics of Reliability of MicrosystemsText books and nd 1. Tummala, Rao R., Fundamentals of Microsystems Packaging, McGraw Hill, 2001.Reference booksBaskewell (Ed), The electronic packaging handbook, CRC Press, 2000. 2. Tummala, Rao R, Microelectronics packaging handbook, McGraw Hill, 2008. 3. Bosshart, Printed Circuit Boards Design and Technology, TataMcGraw Hill, 1988. 4. R.G. Kaduskar and V.B.Baru, Electronic Product design, Wiley India, 2011. 5. R.S.Khandpur, Printed Circuit Board, Tata McGraw Hill, 2005.E-resourcesAn Introduction to Electronics Systems Packaging by Prof. G.V. Mahesh,		Drinted Circuit Deards Anotomy, CAD Teals for DCD Design Misne vie					
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Process Control and Design Challenges. Thermal Considerations: Thermal management, Heat Transfer Fundamentals, Thermal Conductivity and Resistance, Conduction, Convection and Radiation, Importance of Cooling.Unit 5: Testing Technology and Reliability(9Hrs) Basic Concepts, Environmental Interactions. Thermal Mismatch and Fatigue- Failures-Thermo Mechanically Induced, Electrically Induced, Chemically Induced.Electrical Testing: System Level Electrical Testing, Interconnection tests, Active Circuit Testing, Design for Testability, Basics of Reliability of MicrosystemsText booksTextbooks: 1. Tummala, Rao R., Fundamentals of Microsystems Packaging, McGraw Hill, 2001.Blackwell (Ed), The electronic packaging handbook, CRC Press, 2000. 2. Tummala, Rao R, Microelectronics packaging handbook, McGraw Hill, 2008.Bosshart, Printed Circuit Boards Design and Technology, TataMcGraw Hill, 1988.4. R.G. Kaduskar and V.B.Baru, Electronic Product design, Wiley India, 2011.5. R.S.Khandpur, Printed Circuit Board, Tata McGraw Hill, 2005.E-resourcesAn Introduction to Electronics Systems Packaging by Prof. G.V. Mahesh,							
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 Tummala, Rao R, Microelectronics packaging handbook, McGraw Hill, 2008. Bosshart, Printed Circuit Boards Design and Technology, TataMcGraw Hill, 1988. R.G. Kaduskar and V.B.Baru, Electronic Product design, Wiley India, 2011. R.S.Khandpur, Printed Circuit Board, Tata McGraw Hill, 2005. E-resources An Introduction to Electronics Systems Packaging by Prof. G.V. Mahesh, 		1. Blackwell (Ed), The electronic packaging handbook, CRC Press, 2000.					
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5. R.S.Khandpur, Printed Circuit Board, Tata McGraw Hill, 2005.E-resourcesAn Introduction to Electronics Systems Packaging by Prof. G.V. Mahesh,							
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	E-resources						
and other Department of Electronic system Engineering, IISc Bangalore.For more	and other	Department of Electronic system Engineering, IISc Bangalore.For more					
digital details on NPTEL visit <u>http://nptel.iitm.ac.in</u> .	digital						
material	0						

24ECVE509C: High Level Synthesis

Course Category:	Programme Elective-III	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	Digital Logic Design	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course	Upon successful completion of the course, the student will be able to:							
outcomes	CO1		Apply C++ programming concepts and showcase adeptness in designing modular and optimized code.					
	CO2	Design combi techniques	national and se	equential circui	ts using high-l	evel synthesis		
	CO3	Design advanc	ed memory arch	itectures using h	igh-level synthe	sis techniques.		
	CO4	Design princip	les for modular	systems and eff	icient control IO	management.		
	CO5	Design and ir techniques.	nplement diver	se Digital Filte	rs using high-l	evel synthesis		
Contribution		PO1	PO2	PO 3	PO 4	PO5		
of Course	~~ 1			-				
Outcomes	CO1	3		3		2		
towards	cor	2		2		2		
achievement of Program	CO2	3		3		2		
Outcomes	CO3	3		3		2		
(L – Low, M -	CO4	3		3		2		
Medium, H – High)	CO5	3		3		2		
<u> </u>				5				
Course Content		1: ccurate Data 7	Types Introdu	otion Compile	tion Dobug or	(10Hrs)		
Content		l, Header Files	• 1	· •				
	_	d Integer, Fixe		-				
	-	Quantization				-		
		, /, &, , ^,%, B		-		ie operators.		
		amentals of H	_		ction. The Top	-level Design		
		le, Registered				-		
		C++ Synthesi	1 .	-	-			
		uling, Classic		-	-			
		Unrolling, Lo	-			-		
	Count	ter, Optimizing	g the Loop C	ontrol Nested	Loops, Seque	ential Loops,		
	Cond	itions Sharing,	Functions and	Multiple Cond	itional Returns	5.		
	UNIT	II:				(10Hrs)		
	Seque	ential and Co	mbinational	Hardware: In	troduction, Sh	ift Registers,		
	Basic	Shift Registe	er, Shift Reg	ister with Er	able, Shift R	legister with		
	Synch	ronous Clear,	Shift Regist	er with Load	, Shift Regist	ter Template		
	Funct	ion, Class Bas	sed Shift Reg	ister, Helper	Classes for D	esign Reuse,		

	Log2Ceil, NextPow2, Multiplexors, Binary MUX, Automatic Binary to						
	Onehot MUX Optimizations, Manual Optimization of Binary Selection						
	MUXes, One Hot MUX, Finding Leading 1's in a Bit-vector, Finding the						
	Maximum Value in an Array, Absolute Value (abs), Linear Feedback Shif Register (LFSR), Accumulator, Shifters, Barrel shifter, Constant Shifts, Adde						
	Trees, Automatic Tree Balancing, Preventing Automatic Tree Balancing,						
	Coding to Facilitate Automatic Tree Balancing, Lookup Tables (LUT).						
	UNIT III: (8Hrs)						
	Memory Architecture: Introduction, Memory-based Shift Register, Circular						
	Buffer, Memory Organization, Interleaving Memories, Widening the Word						
	Width of Memories, Caching, Using True Single Port RAM as a Dual port						
	RAM, "Windowing" of 1-D Data Streams, 2-D Windowing.						
	UNIT IV: (8Hrs)						
	Hierarchical Design: Introduction, Arrays Shared Between Blocks, Out-of-						
	order Array Access, In-order Array Access, Blocks with Common Interface						
	Control Variables, Passing Control Variables Between Blocks, Connecting						
	Interface Control Variables to Multiple Blocks, Duplicating Control IO.						
	UNIT – V: (9Hrs)						
	Digital Filters: Introduction, FIR Filters, Register Based Filters, External						
	Coefficients, Constant Coefficients, Loadable Coefficients, Symmetric						
	Coefficients, Even Symmetric, Odd Symmetric, Transposed, Systolic, Multi-						
	rate Filtering, Decimation, Interpolation.						
Text books	Text Books						
and Reference	1. Fingeroff, Michael. High-level synthesis: blue book. Xlibris Corporation,						
books	2010.						
	Reference Books						
	1. P Coussy, A Morawiec, "High-level synthesis". Vol. 1. Springer, 2010.						
	2. Vanhoof, Jan. High-Level Synthesis for Real-Time Digital Signal						
	Processing: The CATHEDRAL-II Silicon Compiler. Springer Science &						
	Business Media, 1993.						
E-resources	1. <u>https://www.udemy.com/course/hls-combinational-circuits/#instructor-12</u> .						
and other	2. <u>https://www.udemy.com/course/fpga-design-with-high-level-synthesis-vivado-hls/</u>						
digital							
material							

24ECVE509D: RF IC Design

Course Category:	Programme Elective-III	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	RF& MW Theory,	Continuous Evaluation:	40
	VLSI Design	Semester end Evaluation:	60
		Total Marks:	100

	Upon	successful con	pletion of the	course, the stud	lent will be ab	le to:	
	CO1	CO1 Analyze different characteristics of RF circuits and Systems					
Course	CO2	Design active	and passive C	MOS circuits u	sed in RF app	lications	
outcomes	CO3	Design and m power amplif	neasure perforn iers	nance metrics of	of low-noise a	mplifiers and	
	CO4	Design and an of mixers and	nalyze the fun oscillators	ctionality and	performance c	haracteristics	
	CO5		performance and loop filters	and design	principles o	f frequency	
Contribution		PO1	PO2	PO3	PO4	PO5	
of Course Outcomes	CO1	3	2	2	1	1	
towards achievement	CO2	3	3	3	1	1	
of Program	CO3	3	2	3	1	1	
Outcomes	CO4	3	3	2	1	1	
(1 – Low,							
2 - Medium,	CO5	3	3	2	1	1	
3 - High)							
	UNIT					(9 Hrs)	
		amentals of R					
	Voltage gain, Channel, ACR, AACR, Noise factor, NF of a cascaded system, Sensitivity, HD, Gain compression, P1 dB, Cross modulation, Inter						
		-	-		Cross modu	lation, Inter	
		lation, IM3, IIF smitter and R			wy of modulat	ion sohomos	
		ver architecture			ew of modulat	ion schemes,	
	UNIT			urenneetures		(9 Hrs)	
Course		ve and active c	components for	r CMOS RFIG	C: Review of N	· · · ·	
Content		stor layout, CM	-				
	Transformers, Transmission lines Resonance, Matching, S-parameters, etc. Noise in electrical circuits and NF calculations, Two port noise theory.						
	UNIT III: (9 Hrs)					· · · ·	
		Noise Amplifi					
	•	erated LNA, S vement technic		LNA, Noise o	cancelling LN	As, Linearity	
	-	r Amplifiers:	-	D, E, F and c	other configura	tions, Power	
		ining, Linearity			_		

	UNIT – IV: (9 Hrs)
	Mixers: Specifications, NL system as a mixer, Active mixers, Passive mixers
	Oscillators: Introduction, LC Oscillators, Phase noise
	Introduction to PLLs, Type-I PLLs, Charge pump PLLs: Mathematical model,
	Design issues and Phase noise
	UNIT – V: (9 Hrs)
	Frequency synthesizers: PLL-Based Frequency Synthesizer, Dividers, VCO,
	Ring Oscillators.
	Loop Filter: General Description, Design Approaches, A Complete
	Synthesizer Design Example, Implementation of a Frequency Synthesizer with
	a Fractional Divider.
	Text Books
	1. B. Razavi, "RF Microelectronics", 2 nd Edition, Pearson, 2012.
	2. Thomas H. Lee, "The design of CMOS radio-frequency integrated
	circuits", 2 nd Edition, Cambridge University Press, 2004.
	3. Leung, Bosco, "VLSI for wireless communication", 2 nd Edition, Springer
	Science & Business Media, 2011.
Text books	Reference Books
and	1. Samar K. Saha, "Compact Models for Integrated Circuit
Reference	Design: Conventional Transistors and Beyond", Taylor & Francis, 2015.
books	2. H. Ruiz, R. Pérez, "Linear CMOS RF Power Amplifiers: A
DUURS	Complete Design Workflow", Springer, 2014 edition.
	3. Manganaro, Gabriele, and Domine MW Leenaerts, "Advances in
	analog and RF IC design for wireless communication systems", Academic
	Press, 2013.
	4. Noulis, Thomas, Mixed-signal circuits, CRC Press, 2018.
	5. Rincon-Mora, Gabriel, "Analog IC design with low-dropout
	regulators (LDOs)", McGraw-Hill, 2009.
E-resources	1. RF Integrated Circuits, IIT Delhi, Dr. Shouribrata Chatterjee
and other	https://nptel.ac.in/courses/117102012
digital	
material	

24ECVE510A: LINUX Shell Scripting

Course Category:	Program Elective-IV	Credits:	3
Course Type:	Theory	Lecture-Tutorial-Practice:	3-0-0
Prerequisites:	C Programming	Continuous Evaluation:	40
		Semester End Evaluation:	60
		Total Marks:	100

Course	Upon s	Upon successful completion of the course, the student will be able to:						
outcomes	CO1	Understand th confidently.	Understand the Linux kernel and Graphical Environment to work confidently.					
	CO2 Explore bash shell commands to manage files and directories.							
	CO3	Develop shell	scripts to auto	mate tasks and	d solve probler	ns.		
	CO4	Understand th scripts.	e signals and f	unctions conc	epts to effectiv	vely control shell		
	CO5	Apply regular tasks.	expressions to	validate data	and perform ad	lvanced scripting		
Contributio		PO1	PO2	PO3	PO4	PO5		
n of Course Outcomes towards	CO1	2	1	3	2	2		
achievement of Program	CO2	2	2	2	3	2		
Outcomes: (1 - Low,	CO3	3	3	3	3	2		
2 - Medium, 3 - High)	CO4	2	2	2	3	1		
	CO5	2	2	2	3	3		
Course Content	UNIT-I (9 Hrs) INTRODUCTION TO LINUX KERNALS- What Is Linux, The GNU utilities, The Linux desktop environment, Linux Distributions, Reaching the Command Line, Accessing CLI via a Linux Console Terminal, Graphical Terminal Emulation, GNOME Terminal, Console terminal and xtern Terminal Emulator. UNIT-II (9 Hrs) BASH SHELL COMMANDS- Starting the Shell, Using the Shell Prompt, Interacting with the bash Manual, Navigating the File system, Listing Files and Directories, Handling Files, Managing Directories, Viewing File Contents, Monitoring Programs and Disk Space, Working with Data Files, Exploring Environment Variables, Setting User-Defined Variables, Removing Environment Variables. UNIT-III (9 Hrs) SHELL SCRIPTING- Creating a Script File, Displaying Messages, Structured Commands: Working with the if-then Statement, if-then-else, Nesting ifs, case Command, For Command, While Command, Until Command, Nested loops,							

	Controlling the loops, Processing the Output of a Loop, Practical Examples, Presenting Data: Understanding Input and Output, Redirecting Output and Input in Scripts, Creating Your Own Redirection, Practical Example.
	UNIT-IV (9 Hrs) SCRIPT CONTROL Handling Signals, Running Scripts in Background Mode, Running Scripts without a Hang-Up, Controlling the Job, Being Nice Command, Running Like Clockwork. Basic Script Functions, Returning a Value, Using Variables in Functions, Array variables and functions, Function Recursion, Creating a Library, Using Functions on the Command Line.
	Unit 5: Regular Expression and Alternative Shells(9 Hrs)Types of Regular Expressions, Defining BRE patterns, Extended RegularExpressions, Counting Directory files, Validating Phone number, Working withAlternative Shells: dash Shell, The dash Shell Features, Scripting in dash, The zshShell, Parts of the zsh Shell, Scripting with zsh.
Text Book and Reference Books	 Textbooks: 2. Richard Blum and Christine Bresnahan, "Linux Command Line and Shell Scripting BIBLE", Third Edition, Wiley.
	 References: 5. Neil Matthew and Richard Stones, "Beginning Linux Programming", Fourth Edition, Wiley. 6. B. A. Forouzan and R. F. Gilberg, "Unix and Shell Programming", Cengage Learning. 7. Richard Petersen, "Linux:The Complete Reference", 6th edition, Tata McGraw-Hill. 8. MachteltGarrels, "Introduction to Linux: A Hands on Guide",Third edition,Fultus Corporation.
E-Resources and other digital material	 [1]. <u>https://nptel.ac.in/courses/117106113/</u> [2]. <u>https://vlsiresources.com/linux-and-scripting/</u> [3]. <u>https://nptel.ac.in/courses/106/105/106105172/</u>

Course Category:	Programme Elective-IV	Credits:	3
Course Type:	Theory	Lecture -	3-0-0
		Tutorial -	
		Practice:	
Prerequisites:	C Programming, Microcontrollers &	Continuous	40
	Basic knowledge of embedded	Evaluation:	
	systems.	Semester end	60
		Evaluation:	
		Total Marks:	100

20ECVE510B: Embedded Linux Device Drivers

Course	Upon	successful comp	letion of the cours	se, the stud	ent will be al	ole to:	
Outcomes	CO1	Identify and recall the differences between embedded and desktop Linux,					
		as well as the components of embedded Linux architecture					
	CO2	Apply knowledg	Apply knowledge of memory mapping, interrupt management, and power				
		management to configure embedded systems effectively.					
	CO3	Analyze the role	and integration of	f different di	rivers in the e	mbedded	
		Linux environme	ent				
	CO4		ween various arch	itectures an	d outline the 1	roadmap for	
		application porti	0				
	CO5		components of Lin		graphics and	display	
			n embedded system				
Contribution		PO1	PO2	PO3	PO4	PO5	
of Course	CO1			2		2	
Outcomes	CO2			2	3	2	
towards					_		
achievement	CO3	3		3	3	3	
of Program							
Outcomes	CO4	3		3	3	3	
(1 – Low, 2	CO5			2	1	2	
- Medium, 3							
– High) Course	LINIT	L.L. du ation d	Embedded Linu			(10Hrs)	
Course Content					w Distributio	()	
Content		Embedded Linux Vs Desktop Linux, Embedded Linux Distributions, Embedded Linux Architecture, Kernel Architecture, Hardware abstraction layer (HAL),					
		-	duler, File System	· · · · · · · · · · · · · · · · · · ·			
			-up sequence, GN				
		1 ·	ort Package & Er	1		(10Hrs)	
			l Build Procedure		0	()	
		Interrupt Management, The PCI Subsystem, Timers, UART, Power agement.Memory technology device (MTD), MTD Architecture, Sample					
		Driver for NOR F				, I	
	UNIT	-III: Embedded	Drivers			(8 Hrs)	
	Linux	Serial driver, Eth	ernet driver, I ² C st	ubsystem or	n Linux, Wate	· · ·	
		-	olications, Buildin	•		(10Hrs)	
			on, Application P				
	thread	ls, Operating Syst	em Porting Layer	(OSPL), K	ernel API Dr	iver. Building	

	the Kernel, Building the Root File System, Integrated Development Environment,						
	Kernel Debuggers.						
	UNIT-V:Embedded Graphics (8 Hrs)						
	Linux Desktop Graphics, Introduction to Display Hardware, Embedded Linux						
	Graphics Driver, Windowing Environments.						
Textbooks	Text Books:						
and	1. P Raghvan, Amol Lad, Sriram Neelakandan, "Embedded Linux						
Reference	System Design and						
books	Development", Auerbach Publications.						
	Reference Books:						
	1. Christopher Hallinan, "Embedded Linux Primer: A Practical Real-						
	World Approach", Prentice						
	Hall, 2nd Edition, 2010.						
	2. Karim Yaghmour, "Building Embedded Linux Systems", O'Reilly &						
	Associates						
E-resources	1. https://training.linuxfoundation.org/training/developing-embedded-						
and other	linux-device-drivers/						
digital	2. https://nptel.ac.in/courses/117106113						
material							

24ECVE510C: Communication Buses and Interfaces

Course Category:	Programme Elective-IV	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:	Computer Networks	Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course Outcomes	Upon	successful con	pletion of the	course, the stu	dent will be abl	e to:	
	CO1	Understand th	ne Basics of Se	rial Communic	ation and Data	Transmission	
	CO2		Select and apply a particular Low-Speed serial bus Interface suitable for a given application				
	CO3	•	Analyze and make a decision to use Medium-Speed serial bus Interface for an application.				
	CO4	Examine and application.	Examine and decide a High-Speed serial bus Interface for an application.				
	CO5	Investigate th	e use of Broad	band and wirel	ess Interfaces		
Contribution of Course							
Outcomes towards	CO1	3				2	
achievement of Program	CO2	3				2	
Outcomes (1 – Low, 2 -	CO3	3				2	
Medium, 3– High)	CO4	3				2	
8 /	CO5	3				2	
Course Content	CO532UNIT I: (10 Hrs)Introduction to Serial I/O Communications, Serial I/O Primer: A Short Coursein Data Communications and NetworkingLow-Speed Interfaces: Controller Area Network (CAN), standard CAN,Extended CAN, CAN message, arbitration, message types, CAN bus, Inter-Integrated Circuit (I2C) Bus, RS-232, RS-485.UNIT II: (10 Hrs)Medium-Speed Interfaces: Ethernet, Firewire, Joint Test Action Group(JTAG), Media oriented system transport, Serial Peripheral Interface, UniversalSerial Bus, host and devices, assigning a driver on the host, transfer types,transactionsUNIT III: (9 Hrs)High-Speed Interfaces: 100 Gigabit Ethernet attachment unit interface, Fiberchannel, high-definition multimedia interface (HDMI), hyper transport, optical						

	transport network, PCI express, Synchronous optical network and synchronous digital hierarchy, thunderbolt. UNIT – IV: (9 Hrs) Broadband Interfaces: Broadband Interface concepts, Data over Cable Service Interface Specifications (DOCSIS), Digital subscriber Line, HomePlug (HP), Multimedia over cable alliance, PoweRline Intelligent Metering Evolution (PRIME), X10 Interface.
	UNIT – V (9 Hrs) Wireless Interfaces: Wireless Interfaces, 802.15.4, Bluetooth, Digital Enhanced Cordless Telecommunications (DECT), EnOcean, Industrial Scientific Medical Wireless, Near Field Communications, Ultra-Wideband, Wi-Fi, Wireless HART, ZigBee.
Text books and Reference books	 Text Books: 1.Louis E Frenzel Jr, "Hand book of Serial Communication Interfaces", Newness publications, 2016 2.Jan Axelson, "Serial PortComplete COM Ports, USB Virtual COM Ports, and Ports for Embedded Systems", Lakeview ResearchPublished,2nd edition Mindshare Press 3.Steve Corrigan, "Introduction to the Controller Area Network (CAN)", Texas Instruments, 2016. Reference Books: 1. Jan Axelson, "USB Complete", Penram Publications, 2016 Serial Front Panel Draft Standard VITA 17.1 – 200x
E-resources and other digital material	www.can-cia.org www.pcisig.com www.usb.org

24ECVE510D: Industrial Product Design

Course Category:	Programme Elective-IV	Credits:	3
Course Type:	Theory	Lecture - Tutorial -Practice:	3-0-0
Prerequisites:		Continuous Evaluation:	40
		Semester end Evaluation:	60
		Total Marks:	100

Course Outcomes	Upon	Upon successful completion of the course, the student will be able to					
	CO1	Understand various processes and systems to address human needs by using tangible Electronic Products.					
	CO2		an understandi D and Electroni	• • •	•	•	
	CO3	Illustrate pro techniques.	Illustrate product design concepts using visual communication rechniques.				
	CO4	Apply design information.	n principles lik	te figure-grour	nd relationship	s and visual	
	CO5	Design produc	ct layouts and s	tructures adheri	ng to industrial	standards.	
Contribution of Course		PO1	PO2	PO3	PO4	PO5	
Outcomes towards	CO1	3		2		3	
achievement of Program	CO2	3		2		3	
Outcomes	CO3	3	2	3			
(1 – Low, 2 - Medium, 3–	CO4	3	2	3			
High)	CO5			3	3	3	
Course Content	UNIT I (8Hrs) Introduction to Industrial Design: Introduction to the course, role of ID in the domain of industry, product innovation, Designer's philosophy and role in product design, what is good design (8Hrs) UNIT II (8Hrs) Product Design Methodology: User centred Design methods, Electronic Product Design and Development Methodology, (10 Hrs) UNIT III (10 Hrs) Product Design-Product Analysis: Visual Communication Techniques: Free Hand sketching and drawing techniques for concept presentation, Perspectives, and rendering techniques, colour in design, Engineering drawing practice, exploded views.						
	Desig	UNIT IV (10Hrs) Design Principles: Visual information through design principles, Figure-ground relationship, Visual information distribution, Gestalt principles, Theory of object					

	perception, Symmetry, Asymmetry, Closure, Continuance, Unifying principles of design. Design Expressions. UNIT V (9Hrs) Product Anatomy: Layout design, structure design, standard and non-standard structures, Industrials standards, Product detailing in sheet metal and plastics for easy of assembling.
Text books and Reference books	 Text Books: Peter Z., "German Design Standard Vol. 2", Reddot, 2019. Clarkson P.J, Coleman R. and Keates, S., "Inclusive Design, Design for the whole population", Springer Verlag Gmbh, 2019 Jordan P. W., "Designing Pleasurable Products: An Introduction to the New Human Factors." Taylor and Francis, 2002. Otto K. and Wood K., "Product design: Techniques in Reverse Engineering and New Product development", Prentice Hall, 2001. Cross N. "Engineering Design Methods: Strategies for Product Design", Willey, 2020 Reference Books Cagan J. and Vogel C. M., Creating Breakthrough Products, "Innovation from Product Planning to Program Approval". Pearson Education, 2018. Coats D., "Watches Tell More than Time: Product Design, Information, Quest for elegance" McGraw Hill, 2002 Norman D. A., "The design of everyday things, Basic Books, 2002. Chakrabarty D.," Indian Anthropometric Dimensions for Ergonomic Design Practice", NID, Ahmedabad, 1999. Kelley T. and Littman J. "The Art of Innovation: Lessons in Creativity from Ideo, America's Leading Design Firm, Doubleday", Ver: 4 November 2011 MI – PDN2524, 2001.
E-resources and other digital material	1. http://www.ulrich-eppinger.net/ 2. http://www.npd-solutions.com 3. http://www.qfdi.org 4. http://www.cheshirehenbury.com/rapid/

Course Category:	Audit Course	Credits:	0
Course Type:	Theory	Lecture - Tutorial -Practice:	2-0-0
Prerequisites:	Nil	Continuous Evaluation:	Nil
		Semester end Evaluation:	
		Total Marks:	

Course Outcomes	Upon	successful com	pletion of the c	ourse, the stude	ent will be able	to	
	CO1	Develop the ability to structure and organize scientific papers and technical documents in alignment with academic and industry standards.					
	CO2 Utilize visual aids such as charts, graphs, tables, and figures effective enhance the clarity and impact of technical reports.						
	CO3			preparation, index, figures, and	-	ed techniques	
	CO4			on strategies to l reports clearly			
	CO5	rigorous acad	emic and profe	tific and techr ssional standar and industry se	ds, enhancing e		
Contribution of Course		PO1	PO2	PO3	PO4	PO5	
Outcomes towards	CO1	-	2	-	-	-	
achievement of Program	CO2	-	2	-	-	-	
Outcomes (1 – Low, 2 -	CO3	-	2	-	-	-	
Medium, 3–	CO4	-	2	-	-	-	
High)	CO5	-	2	-	-	-	
Course Content	CO5-2Unit I: Introduction to Scientific Writing(9Hrs)Title, Abstract, Introduction, Materials and Methods, Results, Discussion, Conclusion(9Hrs)Reference Management: Citing, Bibliographies, Acknowledgements, Appendices, Hedging, Paraphrasing, Plagiarism(9Hrs)Unit II: Visual Representation in Technical Reports(9Hrs)Bar Chart, Line Chart, Pie Chart, Area Chart, Cylindrical Chart, Column Bars, Bubble Chart, Flow Diagram, Effective Use of Tables Types of Technical Reports and Writing Guidelines(9Hrs)Unit III: Document Preparation with LaTeX(9Hrs)Introduction to LaTeX, Document Structure: Title, Sections, Labels Table of Contents, Fonts, Colors, Lists, Comments, and Spacing, Special Characters and Symbols in LaTeX(9Hrs)Inserting Equations and Mathematical Symbols, Managing BibTeX Files for Bibliographies, Citing and Formatting References, Styles and Practical						

Text books and Reference books	Unit V: Integrating Tables, Figures, and Equations(9Hrs)Practical Applications of Tables, Figures, and Equations, Advanced LaTeXFeatures for Technical Documents, Using LaTeX for Complex DocumentStructures' Enhancing Document Quality with LaTeXProject: Applying LaTeX in Scientific and Engineering Papers Text Books 1. Barun K Mitra, Effective Technical Communication- A Guide for Scientistsand Engineers, Oxford University Press, ISBN:978019568291.2. LATEX for Beginners, Workbook Edition 5, Document Reference: 3722-2014. Reference Books 1. Goldbort R, Writing for Science, Yale University Press (available on Google Books)2. Day R, How to Write and Publish a Scientific Paper, Cambridge University Press
E-resources	1. Coursera course on Data Visualization
and other	2. EdX course on Technical Report Writing
digital	3. Overleaf: Online LaTeX Editor
material	4. <u>LaTeX Project Website</u>

24ECVE583: Real Time Operating Systems Lab

Course Category:	Laboratory-I	Credits:	1.5
Course Type:	Laboratory	Lecture - Tutorial -Practice:	0-0-3
Prerequisites:	Micro controller and	Continuous Evaluation:	60
	Embedded systems lab	Semester end Evaluation:	40
		Total Marks:	100

Course	Upon	successful com	pletion of the	course, the stud	lent will be abl	e to:				
outcomes	CO1	U		erent RTOS cor	ncepts for real t	time				
			embedded system design.							
	CO2		Developing the RTOS applications for Micro controller boards							
Contribution		PO1	PO1 PO2 PO3 PO4 PO5							
of Course										
Outcomes	CO1	3	3	3	3	3				
towards										
achievement										
of Program										
Outcomes(1	CO2	2	2	2	2	2				
– Low, 2 -										
Medium, 3 –										
High)										
Course		of Experiment								
Content	1.	•	1 0	involves variou	•					
			real-time tasks, such as creation, deletion, and synchronization.							
	2.	-		understand an		scheduling				
		-		e operating syst		0				
	3.	1	0 1	lore the concep						
	4			context of real						
	4.			lustrate the use						
	5	•		nmunication be						
	5.	-		at demonstrate	-					
	6.			ns in a multitas lle interrupts ef	-					
	0.	-	U	m manages and	• • 1	•				
		interrupts		in manages and	responds to c	Xicillai				
	7.	-		anage and man	inulate queues	within the				
	,.	-		em environmen		within the				
	8.			at showcases th		nagement of				
		-		ommunication.						
	9.			erstand and imp	lement signal l	handling				
		1		real-time opera		Ð				
	10			explores memo		nt techniques				
				ne operating sys		1				
	11			1 0 7						
		-								

Lab	Software:1.FreeRTOS
Requirements	2.Open STM32 System Work bench
	 Hardware: 1.The development kits of ARM Developer Kits/ STM32F4 Discovery and Nucleo board. 2. Serial Cables, Network Cables, and recommended power supply for the board.
E-resources and other digital material	 <u>https://training.ti.com/ti-rtos-workshop-series-1-10-welcome</u> <u>https://www.udemy.com/share/101XDy3@Lh74iiF3rMDF83Kk7Od1</u> <u>fQ7-RimKmKiI6HvZDtQmMx77GjLqvx7GSt0-52seWg-J/</u>

24ECVE584: Analog & Mixed Signal Design Lab

Course Category:	Laboratory-II	Credits:
Course Type:	Laboratory	Lecture - Tutorial -Practice:
Prerequisites:	Analog and Mixed	Continuous Evaluation:
	Signal IC Design	Semester end Evaluation:
		Total Marks:

Course	Upon successful completion of the course, the student will be able to:								
outcomes	CO1	Design and analyze analog circuits, with DC, transient, operational, and AC analyses.							
	CO2		Develop and validate the layout through rigorous Design Rule Checks (DRC) and Layout vs. Schematic (LVS) verification.						
	CO3	Extract RC pa analysis.	arameters, back	-annotate desig	gns, and excel i	n post-layout			
Contribution of Course		PO1	PO2	PO3	PO4	PO5			
Outcomes towards	CO1	3	1	3	3	2			
achievement of Program	CO2	3	1	3	3	2			
Outcomes (1 – Low, 2 – Medium, 3 –	CO3	3	1	3	3	2			
High) Course	List of Experiments:								
Content	List of Experiments: Design the following circuits with given specifications, completing the design flow mentioned below: (Minimum 10 Experiments) a. Design and perform the following analysis as per the requirement i. DC ii. Transient iii. Op iv. AC b. Draw the Layout and verify the DRC and LVS c. Extract RC and back annotate the same and verify the Design d. Verify & Optimize for Power and Area to the given constraint 1. Inverter 2. Common source amplifier 3. Common gate amplifier								
	 4. Common drain amplifier 5. Current mirror 6. MOS Differential amplifier 7. Operational amplifier 8. R-2R DAC 								

	9. Ring Oscillator 10. Unity Gain Sampler 11. Phase Locked Loop 12. SAR based ADC
Textbooks and Reference books	Text Books: 1. David A Johns & Ken Martin (2001), "Analog Integrated Circuit Design" John Wiley and Sons. 2. Behzad Razavi (2002), 'Design of Analog CMOS Integrated Circuits' Tata- Mc Graw Hill.

24ECVE592: Capstone project-II

Course Category:	Project	Credits:	1
Course Type:	Project	Lecture - Tutorial -Practice:	0-0-2
Prerequisites:	Capstone Project-I	Continuous Evaluation:	60
		Semester end Evaluation:	40
		Total Marks:	100

Course Description:

For capstone project, a student under the supervision of a faculty member, shall apply the knowledge and hands on technical skills they have gained through course work and lab sessions and submit it to the department in a report form and shall make an oral presentation before the Departmental Committee.

Course Objectives:

- To integrate knowledge acquired across various courses and disciplines throughout the academic program.
- Apply theoretical concepts and practical skills gained in coursework and laboratory sessions to solve real-world problems or address specific challenges within the chosen field of study.
- Provide practical and hands-on experience that prepares them for the expectations and challenges of the workforce in their respective fields.

Course Materials:

- Recommended textbooks and research papers related to the project topic
- Access to relevant software and hardware tools
- Project management software (e.g., Microsoft Project or equivalent)

24ECVE593: Term Paper

Course Category:	Term Paper		Credits:	1
Course Type:	Theory		Lecture - Tutorial -Practice:	0-0-2
Prerequisites:	Research and IPR	Methodology	Continuous Evaluation:	60
			Semester end Evaluation:	40
			Total Marks:	100

Course	Upon successful completion of the course, the student will be able to									
Outcomes	CO1	Identify and a	Identify and analyze the real-world problems beyond the curriculum							
	CO2	Get awareness on current trends in specific area of interest.								
	CO3	Prepare and w survey	Prepare and write technical report on the topic selected after literature survey							
	CO4	Develop commof audiences.	Develop communication skills to explain and interact with a cross section							
Contribution of Course		PO1								
Outcomes towards	CO1	2		1		2				
achievement of Program	CO2	2			1	2				
Outcomes	CO3		3			2				
(1 – Low, 2 - Medium, 3– High)	CO4					2				
Course Content	 The following method is adapted by the department for conducting Term Paper. Term Paper and Project Work are to be carried out individually by M.Tech. students under the supervision of a faculty member. The faculty member allotted to supervise the Term Paper in second Semester shall continue to be the supervisor for the Project Work also. Each faculty member may be permitted to supervise not more than TWO students. If any student/batch left over without supervisors are to be selected by the students themselves. Expected outcomes of Term Paper To carry out literature survey (Reputed international journals / Proceedings of international conferences). To select a technical topic related to area of specialization. 									

SEMESTER III

24ECVE601: Self Learning Course

Course Category:	Program Elective-V	Credits:	3
Course Type	Theory	Lecture-Tutorial-Practice:	3-0-0
Prerequisites:		Continuous Evaluation:	-
		Semester end Evaluation:	-
		Total Marks:	100

Course	The courses under this category shall carry three credits and must have a				
Content	minimum duration of 12 weeks/36 hours. The department will recommend the				
	self-learning courses from the available open courseware. The self- learning				
	courses shall be taken from the list of approved MOOCs providers (SWAYAM / NPTEL/ EDX / Others). They must be approved/ratified in the respective				
	Board of Studies.				

24ECVE691: INTERNSHIP

Course Category:	Internship	Credits:	2
Course Type	Practical	Lecture-Tutorial-Practice	0-0-4
Prerequisites:		Continuous Evaluation:	60
		Semester end Evaluation:	40
		Total Marks:	100

Course Content	The students shall undergo Internship for a period of six weeks in Industry/ Research organizations/ institute of higher learning approved by the Head of the Department during any time after the second semester and shall earn two credits.
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24ECVE692: PROJECT- PART A

Course Category:	Project	Credits:	10
Course Type	Project	Lecture-Tutorial-Practice	0-0-20
Prerequisites:	Research Methodology	Continuous Evaluation:	60
	and IPR	Semester end Evaluation:	40
	Technical Report Writing	Total Marks:	100

	Upon successful completion of the course, the student will be able to:						
Course Outcomes	CO1	Identify a topic in relevant areas of Communication Engineering & Signal Processing.					
	CO2	Review literature to identify gaps and define objectives & scope of the work.					
	CO3		Understand the methods and processes from literature and apply appropriate research methodologies.				
	CO4	Develop an analytical/ computational model/ experimental set-up an prepare a report and develop competence in presenting.					
Contribution of Course Outcomes towards		PO1	PO2	PO3	PO4	PO5	
achievement of Program	CO1	2		1			
Outcomes	CO2	2			1		
(1 – Low, 2 - Medium, 3 –	CO3				3		
High)	CO4		3			2	
Course Content	 Expected outcomes of the Project Work from Part-A: To select a technical topic (from the literature survey carried out as a part of Term Paper) related to specialization in consultation with supervisor and submit an abstract to Project Review Committee PRC at the beginning of the third semester. To critically evaluate the recent literature for the problem identified To carry out the project work under the guidance of supervisor on the topic selected. To submit reports periodically and present before PRC for a review on the progress of work carried out. 						

•	To prepare a report on the work carried out and submit at the end of fourth semester.
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SEMESTER IV

Course Category:	Project	Credits:	16		
Course Type	Project Lecture-Tutorial-Practic		0-0-32		
Prerequisites:	Research Methodology	Continuous Evaluation:	60		
	and IPR	Semester end Evaluation:	40		
	Technical Report Writing	Total Marks:	100		

24ECVE693: PROJECT- PART B

	Upon successful completion of the course, the student will be able to:						
Course Outcomes	CO1	Identify methods and resources to carry out analysis and experiments					
	CO2	Reorganize the procedures with a concern for society, environment and ethics.					
	CO3	Find solutions to complex engineering activities using modern engineering tools.					
	CO4	Analyze and discuss the results to draw valid conclusions.					
	CO5	Prepare a report and defend the work and publish the work in National /International Conferences/journals.					
Contribution of Course		PO1	PO2	PO3	PO4	PO5	
Outcomes towards	CO1	2		1			
achievement of Program	CO2	2			1		
Outcomes	CO3				3		
(1 – Low, 2 - Medium, 3 –	CO4			2		2	
High)	CO5		3			1	
Course Content	•	 To submit reports periodically and present before PRC for a review of the progress of work carried out. To test the work carried out, report the results obtained and perform comparative analysis To publish the paper in Peer reviewed journals/conferences 					